68HC05J5A
68HRC05J5A
68HC705J5A
68HRC705J5A

SPECIFICATION
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GENERAL DESCRIPTION

The MC68HC05J5A is a member of the low-cost high-performance M68 Family of 8-bit microcontroller units (MCUs). The M68HC05 Family is bas the customer-specified integrated circuit design strategy. All MCUs in the use the popular M68HC05 central processing unit (CPU) and are available variety of subsystems, memory sizes and types, and package types.

The MC68HC05J5A is an enhanced version of the MC68HC05J5, with exp RAM, ROM sizes, and an additional 16-bit timer with TCAP. This MCU is av in 20-pin PDIP, 20-pin SOIC, 16-pin PDIP, and 16-pin SOIC packages. The version has four less I/O lines.

Three variation on the MC68HC05J5A device are available; a summary o differences are listed in the following table:

DEVICE	ROM TYPE	OSCILLATOR OPTION	REFERE
MC68HC05J5A	2560 bytes ROM	Crystal/resonator or external clock oscillator	—
MC68HRC05J5A	2560 bytes ROM	RC oscillator	**Append**
MC68HC705J5A	2560 bytes EPROM	Crystal/resonator or external clock oscillator	**Append**
MC68HRC705J5A	2560 bytes EPROM	RC oscillator	**Append**

1.1 FEATURES

The features of the MC68HC05J5A include the following:

- Industry standard M68HC05 CPU core
- Fully static operation with no minimum clock speed
- Power-saving STOP and WAIT modes
- Memory-Mapped Input/Output (I/O) registers
- 2560 Bytes of user ROM with security feature
- 128 Bytes of user RAM
- On-Chip Oscillator:
  - Crystal/Resonator oscillator
  - External clock oscillator
- 15-Bit Multi-function Timer
- 16-Bit Programmable Timer with Input Capture

- 14 Bidirectional I/O pins (10 I/O pins on 16-pin package)
  - PA0-PA5, PB0, and PB3-PB5: with software programmable input p down devices
  - PB1, PB2, PA6 and PA7: open-drained I/O pins with softw programmable pull-up devices
  - PA6, PA7, and PB1: with slow output falling transition feature
  - PA7: with falling-edge interrupt capability
  - PA0-PA3: with maskable rising-edge only or rising-edge and l level interrupt capability
  - 20-pin package: PB1 and PB2, each with 25mA current capability
  - 16-pin package: PB1 with 50mA current sink capability
- Computer Operation Properly (COP) Watchdog
- Low Voltage Reset Circuit
- Illegal Address Reset
- 20-pin PDIP, 20-pin SOIC, 16-pin PDIP, and 16-pin SOIC packages

1.2 MASK OPTIONS

The following mask options are available on the MC68HC05J5A:

MASK	OPTION
STOP instruction convert to WAIT	[Enabled] or [Disabled]
External interrupt pins ($\overline{IRQ}$, PA0-PA3)	[Edge-triggered] or [Edge and level triggered]
Port A and Port B pull-down/pull-up resistors	[Enabled] or [Disabled]
PA0-PA3 external interrupt capability	[Enabled] or [Disabled]
Oscillator Delay Option (internal clock cycles)	[224] or [4064]
Low Voltage Reset	[Enabled] or [Disabled]
COP Watchdog Timer	[Enabled] or [Disabled]

1.3 MCU STRUCTURE

Figure 1-1 shows the structure of MC68HC05J5A MCU.

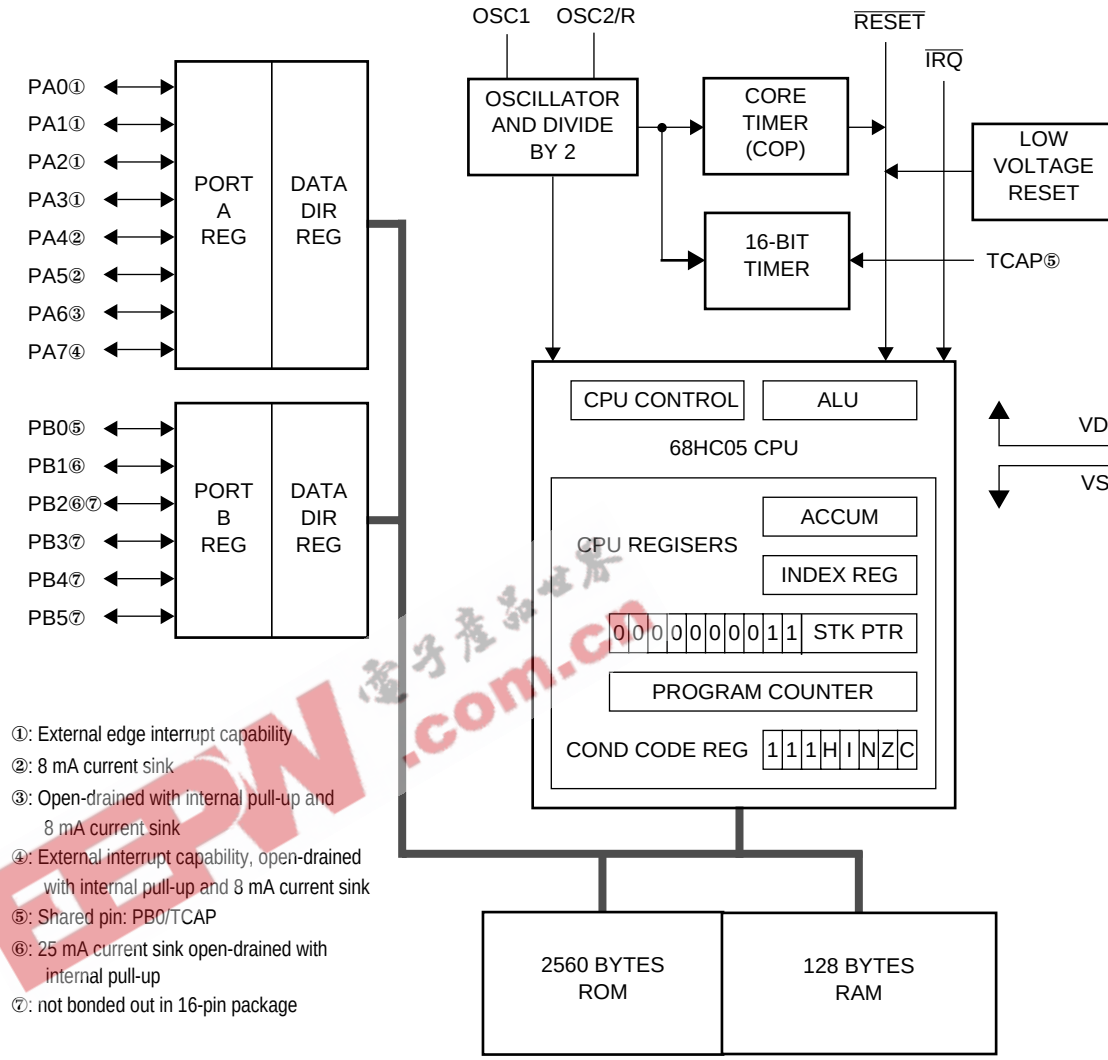
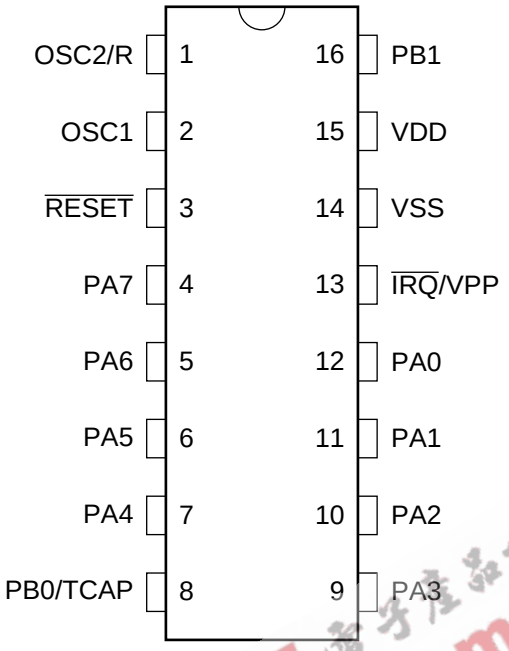


Figure 1-1. MC68HC05J5A Block Diagram

1.4 PIN ASSIGNMENTS



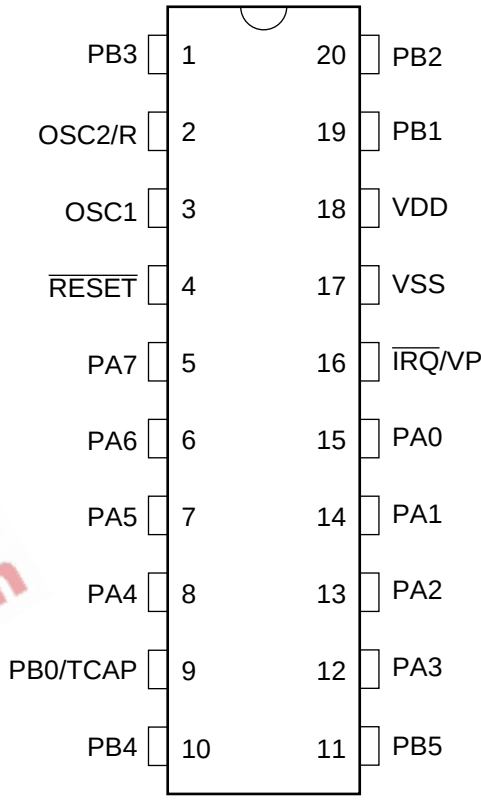


Figure 1-2. Pin Assignments for 16-Pin and 20-Pin Packages

1.5 FUNCTIONAL PIN DESCRIPTION

The following paragraphs give a description of the general function of ea
assigned in **Figure 1-2**.

1.5.1 V_{DD} AND V_{SS}

Power is supplied to the MCU through V_{DD} and V_{SS}. V_{DD} is the positive s
and V_{SS} is ground. The MCU operates from a single power supply.

Very fast signal transitions occur on the MCU pins. The short rise and fal
place very high short-duration current demands on the power supply. To p
noise problems, special care should be taken to provide good power
bypassing at the MCU by using bypass capacitors with good high-frequency
acteristics that are positioned as close to the MCU as possible. Byp
requirements vary, depending on how heavily the MCU pins are loaded.

1.5.2 OSC1, OSC2/R

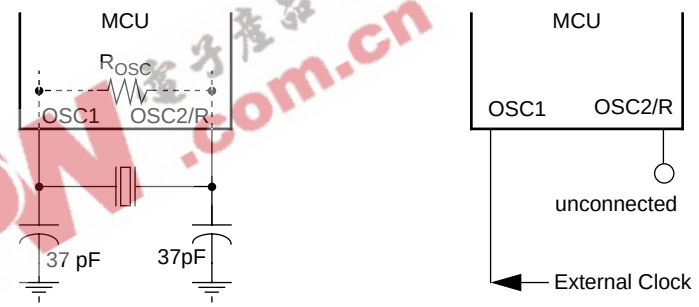
The OSC1 and OSC2/R pins are the connections for the on-chip oscillato
OSC1 and OSC2/R pins can accept the following sets of components:

1. A crystal as shown in **Figure 1-3**(a)
2. A ceramic resonator as shown in **Figure 1-3**(a)
3. An external clock signal as shown in **Figure 1-3**(b)

The frequency, f_{OSC}, of the oscillator or external clock source is divided by produce the internal operating frequency, f_{OP}.

Crystal Oscillator

The circuit in **Figure 1-3**(a) shows a typical oscillator circuit for an AT-cut, p resonant crystal. The crystal manufacturer's recommendations should lowed, as the crystal parameters determine the external component required to provide maximum stability and reliable start-up. The load capac values used in the oscillator circuit design should include all stray capacit The crystal and components should be mounted as close as possible to th for start-up stabilization and to minimize output distortion. An internal s resistor is provided between OSC1 and OSC2/R for the crystal type oscillat



(a) Crystal or ceramic resonator connection

(b) External clock source connection

R_{OSC}: see Section 11. Electrical Specifications.

Figure 1-3. Oscillator Connections

Ceramic Resonator Oscillator

In cost-sensitive applications, a ceramic resonator can be used in place crystal. The circuit in **Figure 1-3**(a) can be used for a ceramic resonator. Th onator manufacturer's recommendations should be followed, as the res parameters determine the external component values required for maximu bility and reliable starting. The load capacitance values used in the oscilla cuit design should include all stray capacitances. The ceramic resonat components should be mounted as close as possible to the pins for start-up lization and to minimize output distortion. An internal start-up resistor is pr between OSC1 and OSC2/R for the ceramic resonator type oscillator.

External Clock

An external clock from another CMOS-compatible device can be connected OSC1 input, with the OSC2/R input not connected, as shown in **Figure 1-3**

1.5.3 $\overline{\text{RESET}}$

This is an I/O pin. This pin can be used as an input to reset the MCU to a start-up state by pulling it to the low state. The $\overline{\text{RESET}}$ pin contains a st diode to discharge any voltage on the pin to V_{DD}, when the power is remov internal pull-up is also connected between this pin and V_{DD}. The $\overline{\text{RESET}}$ pi tains an internal Schmitt trigger to improve its noise immunity as an input. T is an output pin if LVR triggers an internal reset.

1.5.4 $\overline{\text{IRQ}}$ (MASKABLE INTERRUPT REQUEST)

This input pin drives the asynchronous IRQ interrupt function of the CPU. Th interrupt function has a mask option to provide either only negative edge-se triggering or both negative edge-sensitive and low level-sensitive triggering option is selected to include level-sensitive triggering, the $\overline{\text{IRQ}}$ input requi external resistor to V_{DD} for "wired-OR" operation, if desired. The $\overline{\text{IRQ}}$ pin co an internal Schmitt trigger as part of its input to improve noise immunity.

Each of the PA0 through PA3 I/O pins may be connected as an OR functio the IRQ interrupt function by a mask option. This capability allows keyboar applications where the transitions or levels on the I/O pins will behave the as the $\overline{\text{IRQ}}$ pin, except for the inverted phase. The edge or level sen selected by a separate mask option for the $\overline{\text{IRQ}}$ pin also applies to the I/ OR'ed to create the IRQ signal. Besides, PA7 also has falling-edge only in capability whose functionality is controlled by another set of register bits.

1.5.5 PA0-PA7

These eight I/O lines comprise Port A. PA6 and PA7 are open-drained pin pull-up devices whereas PA0 to PA5 are push-pull pins with pull-down de PA4 to PA7 are also capable of sinking 8 mA.

The state of any pin is software programmable and all Port A lines are conf as inputs during power-on or reset. The lower four I/O pins (PA0 to PA3) c connected via an internal OR gate to the IRQ interrupt function enabled by a option. Another independent interrupt source comes from the falling-edge o PA7 interrupt source is associated with a second set of interrupt control bits. All Port A pins except PA6 and PA7 have software programmable pul devices also provided by a mask option. PA6 and PA7 pins have so programmable pull-up devices also provided by the same mask option. P devices on PA6 and PA7 once enabled are always enabled regardless direction configuration, unlike pull-down devices on PA0 to PA5 whic activated only when these pins are configured as input pins.

PA6 and PA7 pins, when configured as output pins, also have slow output edge transition feature to reduce EMI. The falling-edge transition time is 250 ns typical at a specified load of 500 pF, assuming the bus rate is 2 MH slow transition output feature of PA6 and PA7, along with that of PB1 and

can be enabled or disabled by software. Both PA6 and PA7 pins have S trigger input for better noise immunity. V_{IH} and V_{IL} are specified at 2.4V and respectively.

The slow transition feature of PA6 and PA7 pins can be enabled or disab software. Once enabled, slow transition feature is applied to both pins w output mode.

1.5.6 PB0-PB5

NOTE

I/O lines PB2 to PB5 are not available on the 16-pin package.

These six I/O lines comprise Port B. PB0, PB3 to PB5 are push-pull I/O line pull-down resistor. PB1 and PB2 are open-drain I/O lines with pull-up resist

The state of any line is software programmable and is configured as an during power-on or reset. I/O lines PB1 and PB2 have software program pull-up device, whereas PB0, PB3 to PB5 have software programmable pul device, provided by mask option. Pull-up devices on PB1 and PB2 lines enabled are always enabled regardless of pin direction configuration; unlik down devices on PB0, PB3-PB5 lines, which are activated only when the configured as input pin.

Similar to PA6 and PA7, PB1 also has a slow output falling transition feature configured as an output line. PB1 has 25mA sink capability at 0.5V V_{OL}.

PB2 output is one clock cycle (250ns if bus rate is 2MHz) late than other I/ if slow output transition feature is enabled. PB2 has 25mA sink capability a V_{OL}.

NOTE

For the 16-pin package, PB1 and PB2 are bonded to the same pin and is la PB1. This PB1 pin has 50mA sink capability if PB1 and PB2 data register bi are written with the same value at the same write cycle. The falling transitio of PB1 is set at 250ns typical at a specified load of 50pF, assuming that t rate is 2MHz. The slow transition feature on this PB1 pin is longer than PB1 the 20-pin package.

NOTE

If Port Data Register PB1 and PB2 are not written with the same value, P on the 16-pin package will sink 25mA only and the output transition time shorter.

SECTION 2
MEMORY

The MC68HC05J5A has 4K-bytes of addressable memory consisting 32 by
I/O, 128 bytes of user RAM, and 2560 bytes of user ROM, as sho
Figure 2-1.

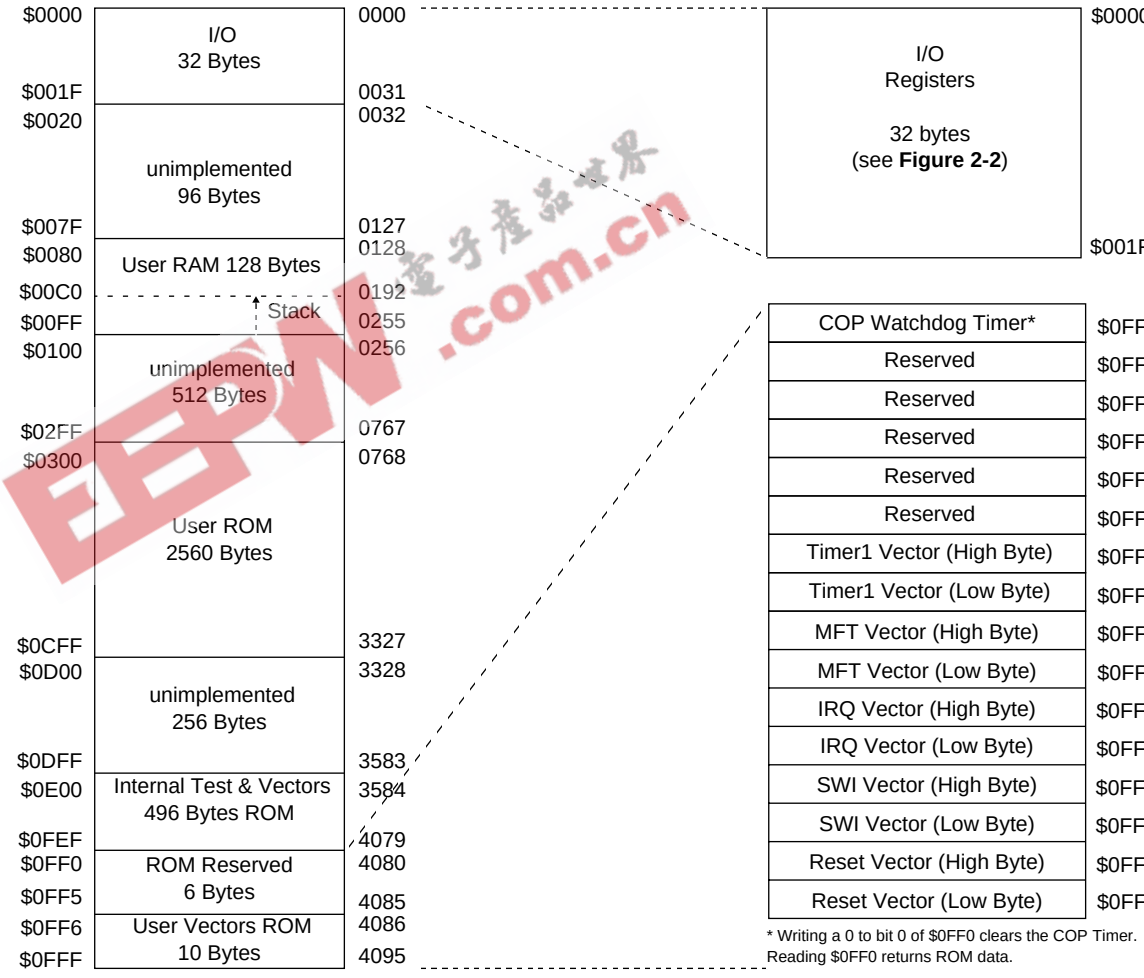


Figure 2-1. MC68HC05J5A Memory Map

2.1 I/O AND CONTROL REGISTERS

The I/O and Control Registers reside in locations $0000-$001F. The overal
nization of these registers is shown in **Figure 2-2**. The bit assignments fo
register are shown in **Figure 2-3** and **Figure 2-4**. Reading from unimplem
bits will return unknown states, and writing to unimplemented bits will be ig

Port A Data Register	$0000
Port B Data Register	$0001
Timer1 Capture Control Register	$0002
unimplemented (1)	$0003
Port A Data Direction Register	$0004
Port B Data Direction Register	$0005
unimplemented (2)	
MFT Control & Status Register	$0008
MFT Counter Register	$0009
IRQ Control & Status Register	$000A
unimplemented (5)	
Port A Pulldown/up Register	$0010
Port B Pulldown/up Register	$0011
Timer1 Registers (4)	$0012 $0015
unimplemented (2)	
Timer1 Registers (4)	$0018 $001B
unimplemented (3)	
Reserved	$001E
Reserved for Test	$001F

Figure 2-2. I/O Registers Memory Map

2.2 RAM

The total RAM consists of 128 bytes (including the stack) at locations
through $00FF. The stack begins at address $00FF and proceeds down to $
Using the stack area for data storage or temporary work locations requires
prevent it from being overwritten due to stacking from an interrupt or subr
call.

2.3 ROM

There are a total of 2570 bytes of user ROM on-chip. This includes 2560 b
user ROM from locations $0300 to $0CFF for user program storage and 10
for user vectors from locations $0FF6 to $0FFF.

2.4 I/O REGISTERS SUMMARY

ADDR	REGISTER	R/W	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
$0000	Port A Data PORTA	R	PA7	PA6	PA5	PA4	PA3	PA2	PA1
		W							
$0001	Port B Data PORTB	R	0	0	PB5	PB4	PB3	PB2	PB1
		W							
$0002	Timer1 Capture Control T1CC	R	TCAPS						
		W							
$0003	*Unimplemented*	*R*							
		W							
$0004	Port A Data Direction DDRA	R	DDRA7	DDRA6	DDRA5	DDRA4	DDRA3	DDRA2	DDRA1
		W							
$0005	Port B Data Direction DDRB	R	SLOWE	0	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1
		W							
$0006	*Unimplemented*	*R*							
		W							
$0007	*Unimplemented*	*R*							
		W							
$0008	MFT Ctrl/Status TCSR	R	TOF	RTIF	TOFE	RTIE	0	0	RT1
		W					TOFR	RTIFR	
$0009	MFT Counter TCR	R	TMR7	TMR6	TMR5	TMR4	TMR3	TMR2	TMR1
		W							
$000A	IRQ Control/Status ICSR	R	IRQE	IRQE1	0	0	IRQF	IRQF1	0
		W				R			IRQR
$000B	*Unimplemented*	*R*							
		W							
$000C	*Unimplemented*	*R*							
		W							
$000D	*Unimplemented*	*R*							
		W							
$000E	*Unimplemented*	*R*							
		W							
$000F	*Unimplemented*	*R*							
		W							

unimplemented bits reserved bits

Figure 2-3. I/O Registers $0000-$000F

ADDR	REGISTER	R/W	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
$0010	Port A Pull-down/up PDURA	R							
		W	PURA7	PURA6	PDRA5	PDRA4	PDRA3	PDRA2	PDRA1
$0011	Port B Pull-down/up PDURB	R							
		W			PDRB5	PDRB4	PDRB3	PURB2	PURB1
$0012	Timer1 Control T1CR	R	ICIE	0	T1OIE	0	0	0	IEDGE
		W							
$0013	Timer1 Status T1SR	R	ICF	0	T1OF	0	0	0	0
		W							
$0014	Input Capture High ICH	R	BIT15	BIT14	BIT13	BIT12	BIT11	BIT10	BIT9
		W							
$0015	Input Capture Low ICL	R	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1
		W							
$0016	*Unimplemented*	*R*							
		W							
$0017	*Unimplemented*	*R*							
		W							
$0018	Timer1 Counter High TCNTH	R	BIT15	BIT14	BIT13	BIT12	BIT11	BIT10	BIT9
		W							
$0019	Timer1 Counter Low TCNTL	R	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1
		W							
$001A	Alt. Counter High ACNTH	R	BIT15	BIT14	BIT13	BIT12	BIT11	BIT10	BIT9
		W							
$001B	Alt. Counter Low ACNTL	R	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1
		W							
$001C	*Unimplemented*	*R*							
		W							
$001D	*Unimplemented*	*R*							
		W							
$001E	*Reserved*	*R*	R	R	R	R	R	R	R
		W							
$001F	*Reserved*	*R*	R	R	R	R	R	R	R
		W							

unimplemented bits reserved bits

Figure 2-4. I/O Registers $0010-$001F

SECTION 3
CENTRAL PROCESSING UNIT

The MC68HC05J5A has an 4k-bytes memory map. The stack has only 64
Therefore, the stack pointer has been reduced to only 6 bits and wi
decrement down to $00C0 and then wrap-around to $00FF. All other instru
and registers behave as described in this chapter.

3.1 REGISTERS

The MCU contains five registers which are hard-wired within the CPU and a
part of the memory map. These five registers are shown in **Figure 3-1** a
described in the following paragraphs.

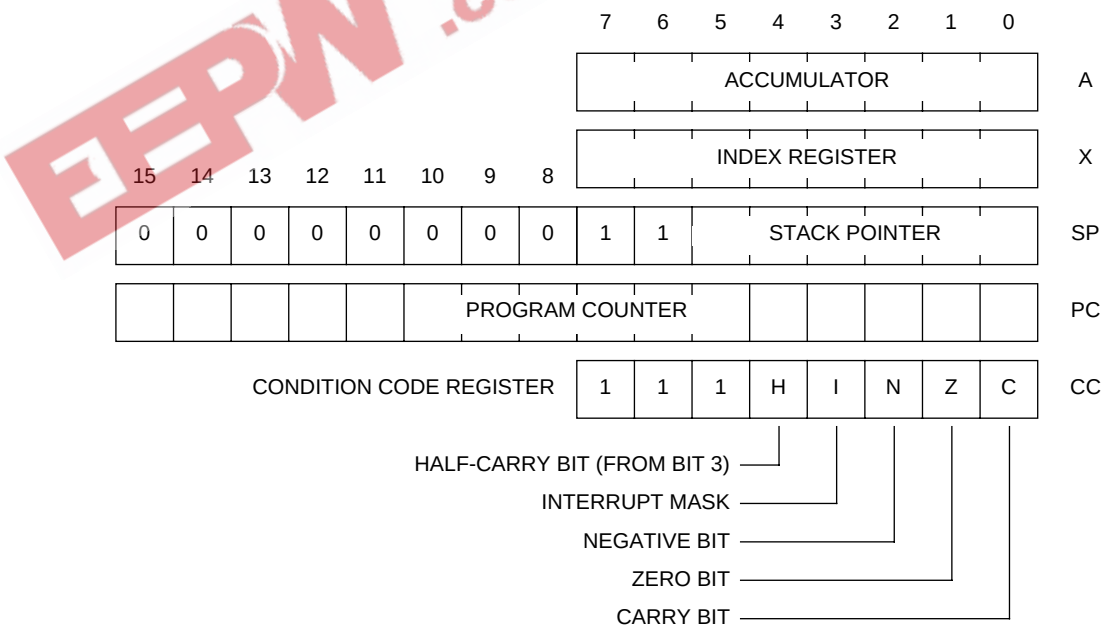


Figure 3-1. MC68HC05 Programming Model

3.2 ACCUMULATOR (A)

The accumulator is a general purpose 8-bit register as shown in **Figure 3-** CPU uses the accumulator to hold operands and results of arithmetic calcu or non-arithmetic operations. The accumulator is not affected by a reset device.

3.3 INDEX REGISTER (X)

The index register shown in **Figure 3-1** is an 8-bit register that can perfo functions:

- Indexed addressing
- Temporary storage

In indexed addressing with no offset, the index register contains the low b the operand address, and the high byte is assumed to be $00. In in addressing with an 8-bit offset, the CPU finds the operand address by addi index register content to an 8-bit immediate value. In indexed addressing 16-bit offset, the CPU finds the operand address by adding the index r content to a 16-bit immediate value.

The index register can also serve as an auxiliary accumulator for tem storage. The index register is not affected by a reset of the device.

3.4 STACK POINTER (SP)

The stack pointer shown in **Figure 3-1** is a 16-bit register. In MCU device memory space less than 64k-bytes the unimplemented upper address lin ignored. The stack pointer contains the address of the next free location stack. During a reset or the reset stack pointer (RSP) instruction, the stack p is set to $00FF. The stack pointer is then decremented as data is pushed on stack and incremented as data is pulled off the stack.

When accessing memory, the ten most significant bits are permanently 0000000011. The six least significant register bits are appended to these te bits to produce an address within the range of $00FF to $00C0. Subroutine interrupts may use up to 64($C0) locations. If 64 locations are exceede stack pointer wraps around and overwrites the previously stored informa subroutine call occupies two locations on the stack and an interrupt use locations.

3.5 PROGRAM COUNTER (PC)

The program counter shown in **Figure 3-1** is a 16-bit register. In MCU d with memory space less than 64k-bytes the unimplemented upper addres are ignored. The program counter contains the address of the next instruc operand to be fetched.

Normally, the address in the program counter increments to the next seq memory location every time an instruction or operand is fetched. Jump, b and interrupt operations load the program counter with an address other tha of the next sequential location.

3.6 CONDITION CODE REGISTER (CCR)

The CCR shown in **Figure 3-1** is a 5-bit register in which four bits are u indicate the results of the instruction just executed. The fifth bit is the in mask. These bits can be individually tested by a program, and specific actio be taken as a result of their states. The condition code register should be th of as having three additional upper bits that are always ones. Only the in mask is affected by a reset of the device. The following paragraphs expla functions of the lower five bits of the condition code register.

3.6.1 Half Carry Bit (H-Bit)

When the half-carry bit is set, it means that a carry occurred between bits 3 of the accumulator during the last ADD or ADC (add with carry) operatio half-carry bit is required for binary-coded decimal (BCD) arithmetic operatio

3.6.2 Interrupt Mask (I-Bit)

When the interrupt mask is set, the internal and external interrupts are dis Interrupts are enabled when the interrupt mask is cleared. When an in occurs, the interrupt mask is automatically set after the CPU registers are on the stack, but before the interrupt vector is fetched. If an interrupt r occurs while the interrupt mask is set, the interrupt request is latched. No the interrupt is processed as soon as the interrupt mask is cleared.

A return from interrupt (RTI) instruction pulls the CPU registers from the restoring the interrupt mask to its state before the interrupt was encountered any reset, the interrupt mask is set and can only be cleared by the Clea (CLI), or WAIT instructions.

3.6.3 Negative Bit (N-Bit)

The negative bit is set when the result of the last arithmetic operation, operation, or data manipulation was negative. (Bit 7 of the result was a one.)

The negative bit can also be used to check an often tested flag by assigni flag to bit 7 of a register or memory location. Loading the accumulator w contents of that register or location then sets or clears the negative bit acc to the state of the flag.

3.6.4 Zero Bit (Z-Bit)

The zero bit is set when the result of the last arithmetic operation, operation, data manipulation, or data load operation was zero.

3.6.5 Carry/Borrow Bit (C-Bit)

The carry/borrow bit is set when a carry out of bit 7 of the accumulator oc during the last arithmetic operation, logical operation, or data manipulatio carry/borrow bit is also set or cleared during bit test and branch instructio during shifts and rotates. This bit is neither set by an INC nor by a DEC instr

SECTION 4
INTERRUPTS

The MCU can be interrupted in six different ways:

- Non-maskable Software Interrupt Instruction (SWI)
- External Asynchronous Interrupt ($\overline{IRQ}$)
- Optional External Interrupt via IRQ on PA0-PA3 (by a mask option)
- External Interrupt via IRQ on PA7
- Multi-Function Timer (MFT)
- 16-Bit Timer Interrupt (Timer1)

4.1 CPU INTERRUPT PROCESSING

Interrupts cause the processor to save register contents on the stack and the interrupt mask (I-bit) to prevent additional interrupts. Unlike RESET, har interrupts do not cause the current instruction execution to be halted, but ar sidered pending until the current instruction is complete.

If interrupts are not masked (I-bit in the CCR is clear) and the corresponding rupt enable bit is set the processor will proceed with interrupt processing. wise, the next instruction is fetched and executed. If an interrupt occu processor completes the current instruction, then stacks the current CPU r states, sets the I-bit to inhibit further interrupts, and finally checks the p hardware interrupts. If more than one interrupt is pending following the st operation, the interrupt with the highest vector location shown in **Table 4-1** serviced first. The SWI is executed the same as any other instruction, rega of the I-bit state.

When an interrupt is to be processed the CPU fetches the address of the priate interrupt software service routine from the vector table at locations thru $0FFF as defined in **Table 4-1**.

Table 4-1. Vector Address for Interrupts and Reset

Register	Flag Name	Interrupts	CPU Interrupt	Vector Address
N/A	N/A	Reset	RESET	$0FFE-$0FFF
N/A	N/A	Software	SWI	$0FFC-$0FFD
ICSR	IRQF/IRQF1	External Interrupt	IRQ	$0FFA-$0FFB
TCSR	TOF	MFT Overflow	MFT	$0FF8-$0FF9
TCSR	RTIF	Real Time Interrupt	MFT	$0FF8-$0FF9
T1SR	T1OF, ICF	Timer1 Interrupt	TIMER1	$0FF6-$0FF7

An RTI instruction is used to signify when the interrupt software service rou
completed. The RTI instruction causes the register contents to be recovere
the stack and normal processing to resume at the next instruction that was
executed when the interrupt took place. **Figure 4-1** shows the sequence of
that occur during interrupt processing.

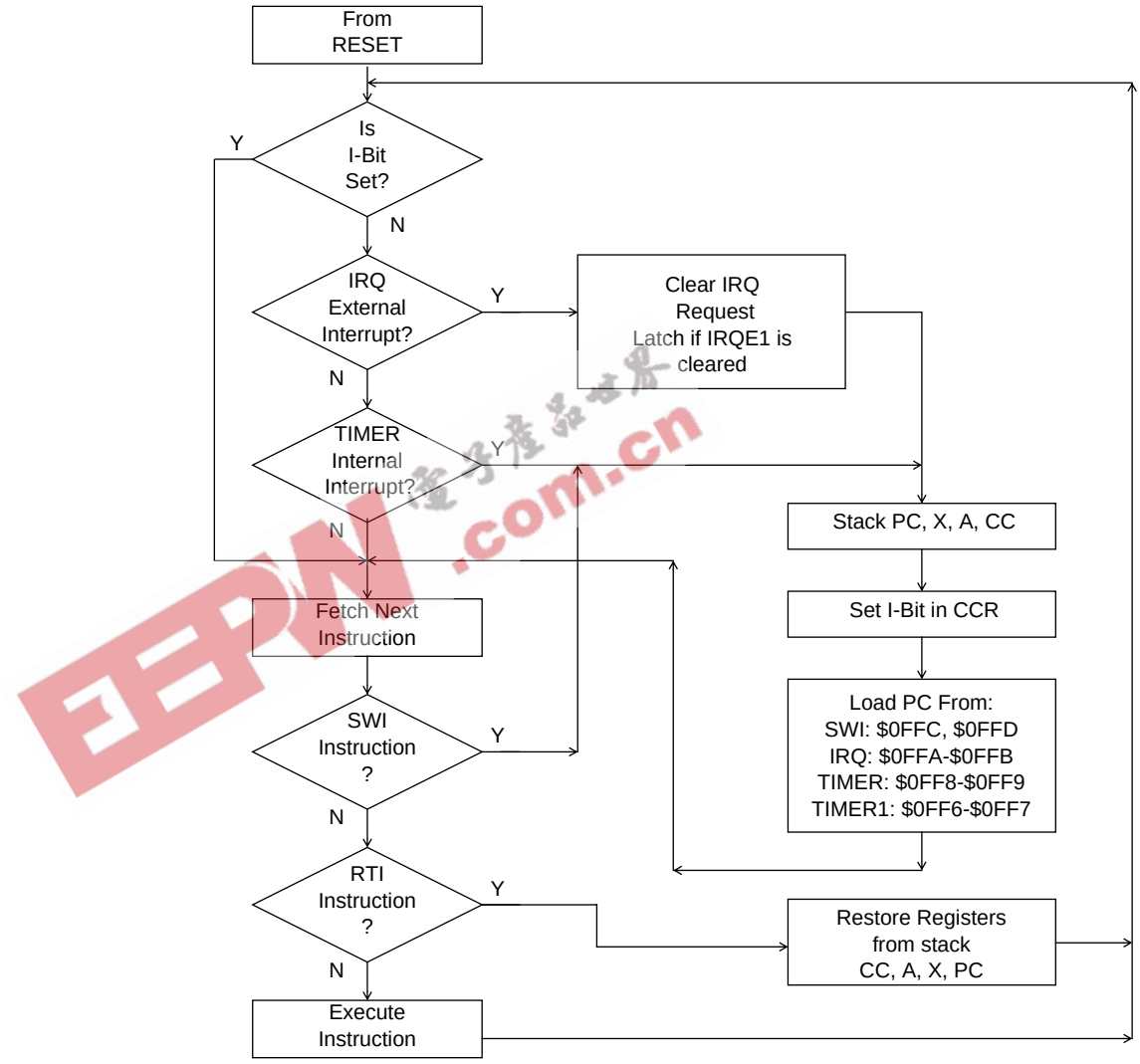


Figure 4-1. Interrupt Processing Flowchart

4.2 RESET INTERRUPT SEQUENCE

The RESET function is not in the strictest sense an interrupt; however, it is
upon in a similar manner as shown in **Figure 4-1**. A low level input on the $\overline{R}$
pin or an internally generated RST signal causes the program to vector to its
ing address which is specified by the contents of memory locations $0FF
$0FFF. The I-bit in the condition code register is also set.

4.3 SOFTWARE INTERRUPT (SWI)

The SWI is an executable instruction and a non-maskable interrupt since it cuted regardless of the state of the I-bit in the CCR. As with any instruction rupts pending during the previous instruction will be serviced before th opcode is fetched. The interrupt service routine address is specified by th tents of memory locations $0FFC and $0FFD.

4.4 HARDWARE INTERRUPTS

All hardware interrupts except RESET are maskable by the I-bit in the CCR I-bit is set, all hardware interrupts (internal and external) are disabled. Cl the I-bit enables the hardware interrupts. There are two types of hardware rupts which are explained in the following sections.

4.5 EXTERNAL INTERRUPT ($\overline{IRQ}$)

The $\overline{IRQ}$ pin provides an asynchronous interrupt to the CPU. A block diag the IRQ function is shown in **Figure 4-2**.

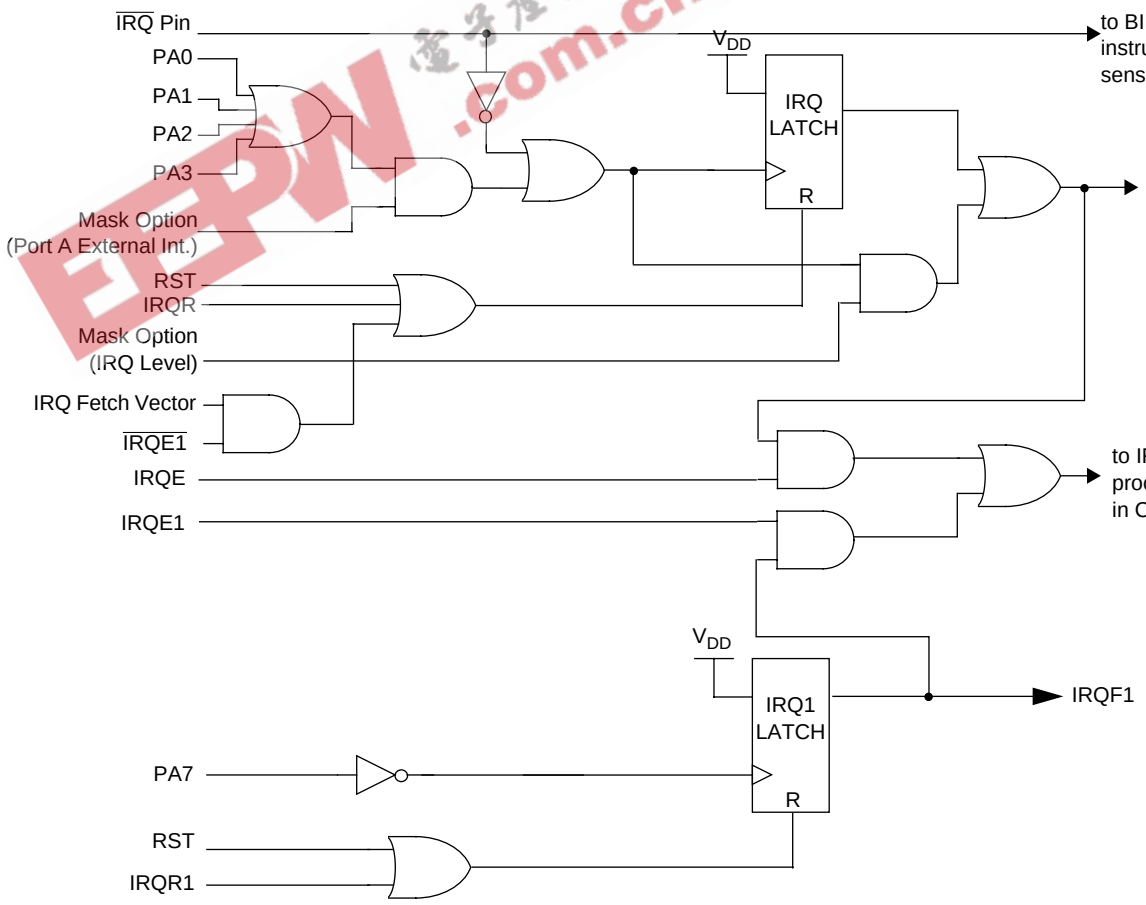


Figure 4-2. IRQ Function Block Diagram

The $\overline{IRQ}$ pin is a source of IRQ interrupts and a mask option can also enal other four lower Port A pins (PA0 thru PA3) to act as other IRQ interrupt sou

The last source of IRQ interrupt comes from PA7 whenever there is a fallin on PA7 and IRQE1 is enabled. There is no mask option associated with PA rupt.

Refer to **Figure 4-2** for the following descriptions. IRQ interrupt source from IRQ and IRQ1 latches. The IRQ latch will be set on the falling edge $\overline{IRQ}$ pin or on any rising edge of PA0-3 pins if PA0-3 interrupts have been en The IRQ1 latch will be set on the falling edge of PA7 if PA7 interrupt has enabled. If "edge-only" sensitivity is chosen by a mask option, only the IRQ output can activate an IRQF flag which creates a request to the CPU to ge the IRQ interrupt sequence. This makes the IRQ interrupt sensitive to the fol cases:

1. Falling edge on the $\overline{IRQ}$ pin.
2. Rising edge on any PA0-PA3 pin with IRQ enabled (via mask option)

If level sensitivity is chosen, the rising edge signal on the clock input of th latch can also activate an IRQF flag which creates an IRQ request to the C generate the IRQ interrupt sequence. This makes the IRQ interrupt sensi the following cases:

1. Low level on the $\overline{IRQ}$ pin.
2. Falling edge on the $\overline{IRQ}$ pin.
3. High level on any PA0- PA3 pin with IRQ enabled (via mask option).
4. Rising edge on any PA0- PA3 pin with IRQ enabled (via mask option

The IRQE enable bit controls whether an active IRQF flag can generate a interrupt sequence. This interrupt is serviced by the interrupt service r located at the address specified by the contents of $0FFA and $0FFB.

The IRQ latch is automatically cleared by entering the interrupt service rou IRQE1 enable bit is cleared. If IRQE1 enable bit is also set, the only way of ing IRQF is by writing a logic one to the IRQR acknowledge bit. Writing a log to the IRQR acknowledge bit in the ICSR is the other way of clearing IRQ regardless of the status of the IRQE1 bit, besides IRQ vector fetch. This tional reset of IRQF flag provides a way for the user to differentiate the in sources from IRQ and IRQ1 latches and also to make it J1A compatible interrupt is not used. As long as the output state of the IRQF flag bit is act CPU will continuously re-enter the IRQ interrupt sequence until the active s removed or the IRQE enable bit is cleared.

PA7 interrupt source, if enabled by IRQE1 enable bit, triggers IRQ interr PA7 falling edge only. The IRQ1 latch (IRQF1 flag) can ONLY be cleared by a logic one to the IRQR1 acknowledge bit in the ICSR. IRQ vector fetch ca clear IRQF1 flag. IRQ interrupt caused by PA7 falling edge also vectors to and $0FFB.

4.5.1 IRQ CONTROL/STATUS REGISTER (ICSR) $0A

The IRQ interrupt function is controlled by the ICSR located at $000A. All u
bits in the ICSR will read as logic zeros. The IRQF, IRQF1, IRQE1 bits are c
and IRQE bit is set by reset.

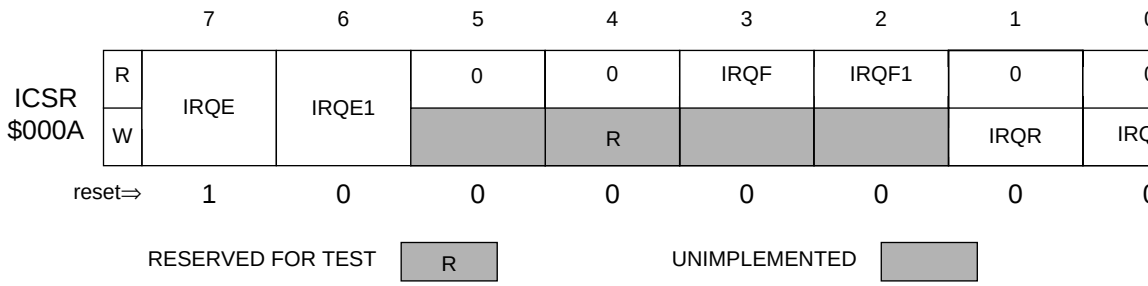


Figure 4-3. IRQ Status & Control Register

IRQR 1 - PA7 Interrupt Acknowledge

The IRQR1 acknowledge bit clears an IRQ interrupt triggered by a fallin
on PA7 by clearing the IRQ1 latch. The IRQR1 acknowledge bit will alway
as a logic zero.

1 = Writing a logic one to the IRQR1 acknowledge bit will clear the IR
latch.

0 = Writing a logic zero to the IRQR1 acknowledge bit will have no ef
on the IRQ1 latch.

IRQR - IRQ Interrupt Acknowledge

The IRQR acknowledge bit clears an IRQ interrupt by clearing the IRQ
The IRQR acknowledge bit will always read as a logic zero.

1 = Writing a logic one to the IRQR acknowledge bit will clear the
latch.

0 = Writing a logic zero to the IRQR acknowledge bit will have no ef
on the IRQ latch.

IRQF1 - PA7 Interrupt Request Flag

Writing to the IRQF1 flag bit will have no effect on it. If the additional set
IRQF1 flag bit is not cleared in the IRQ service routine and the IRQE1
bit remains set the CPU will re-enter the IRQ interrupt sequence contin
until either the IRQF1 flag bit or the IRQE1 enable bit is cleared. The
latch is cleared by reset.

1 = Indicates that an IRQ request triggered by a falling edge on PA
pending.

0 = Indicates that no IRQ request triggered by a falling edge on PA
pending. The IRQF1 flag bit can ONLY be cleared by writing a l
one to the IRQR1 acknowledge bit. Doing so before exiting
service routine will mask out additional occurrences of the IRQF

IRQF - IRQ Interrupt Request Flag

Writing to the IRQF flag bit will have no effect on it. If the additional setting o flag bit is not cleared in the IRQ service routine and the IRQE enable bit re set the CPU will re-enter the IRQ interrupt sequence continuously until eith IRQF flag bit or the IRQE enable bit is clear. The IRQF latch is cleared by re

1 = Indicates that an IRQ request is pending.

0 = Indicates that no IRQ request triggered by pins PA0-3 or $\overline{\text{IRQ}}$ pending. The IRQF flag bit is cleared once the IRQ vector is fetc AND if IRQE1 is also cleared. If IRQE1 is set, then the only wa clearing IRQF flag is by writing a logic one to IRQR bit. The IR flag bit can be cleared, regardless of the status of the IRQE1 bit writing a logic one to the IRQR acknowledge bit to clear the latch and also conditioning the external IRQ sources to be inac (if the level sensitive interrupts are enabled via mask option). Do so before exiting the service routine will mask out additio occurrences of the IRQF.

IRQE1 - PA7 Interrupt Enable

The IRQE1 bit enables/disables the IRQF1 flag bit to initiate an IRQ in sequence.

1 = Enables IRQF1 interrupt, that is, the IRQF1 flag bit can generate interrupt sequence. Execution of the STOP or WAIT instructions leave the IRQE1 bit to be UNAFFECTED.

0 = The IRQF1 flag bit cannot generate an interrupt sequence. Re clears the IRQE1 enable bit, thereby disabling PA7 interrupts.

IRQE - IRQ Interrupt Enable

The IRQE bit enables/disables the IRQF flag bit to initiate an IRQ in sequence.

1 = Enables IRQF interrupt, that is, the IRQF flag bit can generate interrupt sequence. Reset sets the IRQE enable bit, ther enabling IRQ interrupts once the I-bit is cleared. Execution of STOP or WAIT instructions causes the IRQE bit to be set in orde allow the external IRQ to exit these modes.

0 = The IRQF flag bit cannot generate an interrupt sequence.

4.5.2 OPTIONAL EXTERNAL INTERRUPTS (PA0-PA3)

The IRQ interrupt can also be triggered by the inputs on the PA0 thru PA pins if enabled by a single mask option. If enabled, the lower four bits of can activate the IRQ interrupt function, and the interrupt operation will same as for inputs to the $\overline{\text{IRQ}}$ pin. This mask option of PA0-3 interrupt allow these input pins to be OR'ed with the input present on the $\overline{\text{IRQ}}$ pin. All PA PA3 pins must be selected as a group as an additional IRQ interrupt. All the interrupt sources are also controlled by the IRQE enable bit.

NOTE

The BIH and BIL instructions will only apply to the level on the $\overline{IRQ}$ pin itse not to the output of the logic OR function with the PA0 thru PA3 pins. The s the individual Port A pins can be checked by reading the appropriate Port as inputs.

NOTE

If enabled, the PA0 thru PA3 and PA7 pins will cause an IRQ interrupt rega of whether these pins are configured as inputs or outputs.

4.5.3 TIMER INTERRUPT (MFT)

The TIMER interrupt is generated by the multi-function timer when either a overflow or a real time interrupt has occurred as described in **Section 8**. The rupt flags and enable bits for the Timer interrupts are located in the Timer C & Status Register (TCSR) located at $0008. The I-bit in the CCR must be c order for the TIMER interrupt to be enabled. Either of these two interrupts w tor to the same interrupt service routine located at the address specified contents of memory locations $0FF8 and $0FF9.

4.5.4 TIMER1 INTERRUPT (16-BIT TIMER)

The Timer1 interrupt is generated by the 16-bit Timer when either a timer1 flow or a input capture has occurred as described in **Section 9**. The interrup and enable bits for the Timer1 interrupt are located in the Timer1 Control & Register (T1CR & T1SR) located at $0012, $0013. The I-bit in the CCR m cleared in order to enable the Timer1. Either of these two interrupts will ve the same interrupt service routine located at the address specified by the co of memory locations $0FF6 and $0FF7.

SECTION 5
RESETS

The MCU can be reset from five sources: one external input and four i
restart conditions.

- Initial power up of device (power on reset)
- A logic zero applied to the $\overline{\text{RESET}}$ pin (external reset)
- Timeout of the COP watchdog (COP reset)
- Low voltage applied to the device (LVR reset)
- Fetch of an opcode from an address not in the memory map (ill
address reset)

Figure 5-1 shows a block diagram of the reset sources and their interaction

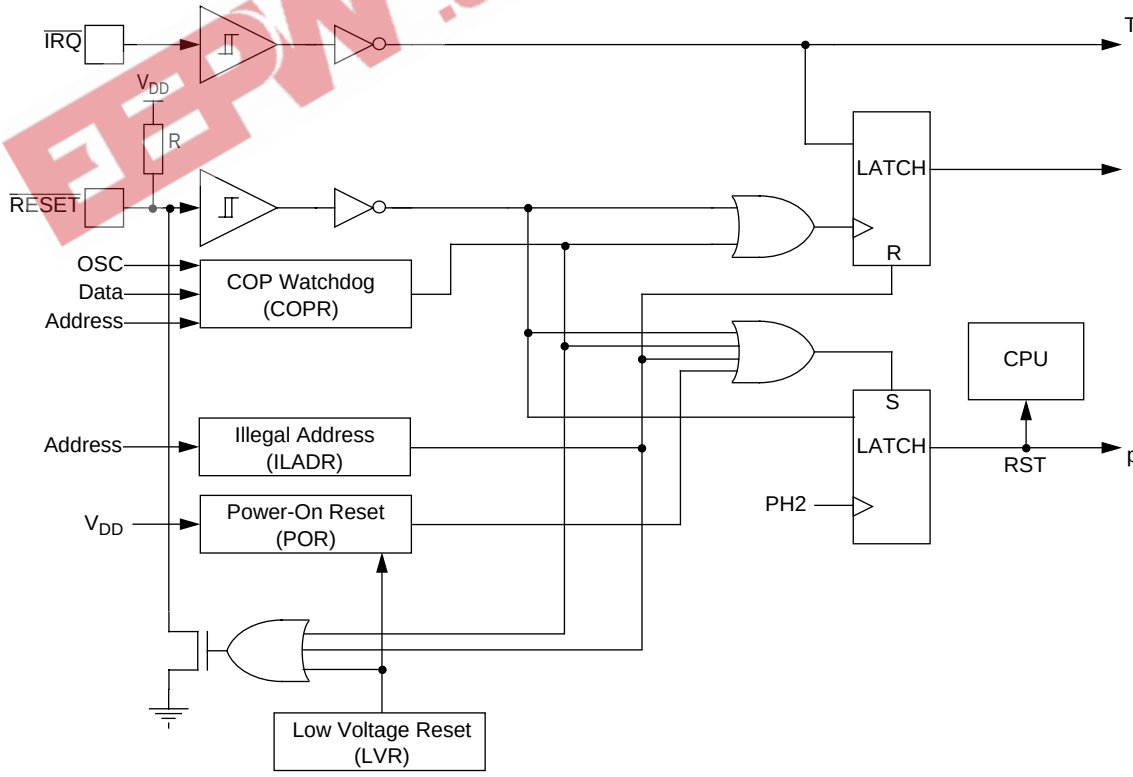


Figure 5-1. Reset Block Diagram

5.1 EXTERNAL RESET ($\overline{\text{RESET}}$)

The $\overline{\text{RESET}}$ pin is the only external source of a reset. This pin is connecte
Schmitt trigger input gate to provide an upper and lower threshold voltage
rated by a minimum amount of hysteresis. This external reset occurs wh
the $\overline{\text{RESET}}$ pin is pulled below the lower threshold and remains in reset u
$\overline{\text{RESET}}$ pin rises above the upper threshold. This active low input will gener
RST signal and reset the CPU and peripherals. This pin is also an outp
whenever the LVR triggers an internal reset. Termination of the external R
input or the internal COP Watchdog reset or LVR are the only reset sourc
can alter the operating mode of the MCU.

NOTE

Activation of the RST signal is generally referred to as reset of the device,
otherwise specified.

5.2 INTERNAL RESETS

The four internally generated resets are the initial power-on reset functio
COP Watchdog Timer reset, the illegal address detector reset and the low v
reset (LVR). Termination of the external RESET input or the internal COP W
dog Timer or LVR are the only reset sources that can alter the operating m
the MCU. The other internal resets will not have any effect on the mode of
tion when their reset state ends.

5.2.1 POWER-ON RESET (POR)

The internal POR is generated on power-up to allow the clock oscillator to
lize. The POR is strictly for power turn-on conditions and is not able to de
drop in the power supply voltage (brown-out). There is an oscillator stal
delay after the oscillator becomes active. The delay time could be 224 or 4
internal processor bus clock cycles (PH2) which is a mask option.

The POR will generate the RST signal which will reset the CPU. If any othe
function is active at the end of this delay time, the RST signal will remain
reset condition until the other reset condition(s) end.

5.2.2 COMPUTER OPERATING PROPERLY RESET (COPR)

The internal COPR reset is generated automatically (if the COP is enabled
time-out of the COP Watchdog Timer. This time-out occurs if the counter
COP Watchdog Timer is not reset (cleared) within a specific time by a so
reset sequence. The COP Watchdog Timer can be disabled by a mask
Refer to **Section 8.2** for more information on this time-out feature. COP res
forces the $\overline{\text{RESET}}$ pin low

The COPR will generate the RST signal which will reset the CPU and peripherals. Also, the COPR will establish the mode of operation based state of the $\overline{IRQ}$ pin at the time the COPR signal ends. If the voltage on th pin is at the V_{TST} level, the state of the PB0 pin during the last rising edge $\overline{RESET}$ pin will determine which Test Mode (Internal or Expanded) the MC be in. If the voltage at the $\overline{IRQ}$ pin is in the normal operating range (V_{SS} to the MCU will enter Single-Chip Mode when the COPR signal ends. If any reset function is active at the end of the COPR reset signal, the RST sign remain in the reset condition until the other reset condition(s) end.

5.2.3 LOW VOLTAGE RESET (LVR)

The internal LVR reset is generated when V_{DD} falls below the specified LV ger value V_{LVR} for at least one t_{CYC}. In typical applications, the power supp coupling circuit will eliminate negative-going voltage glitches of less tha t_{CYC}. This reset will hold the MCU in the reset state until V_{DD} rises above Whenever V_{DD} is above V_{LVR} and below 4.5V, the MCU is guaranteed to o although not within specification. The output from the LVR is connected dire the internal reset circuitry and also forces the $\overline{RESET}$ pin low. The interna will be removed once the power supply voltage rises above V_{LVR}, at which normal power-on-reset sequence occurs.

5.2.4 ILLEGAL ADDRESS RESET (ILADR)

The internal ILADR reset is generated when an instruction opcode fetch from an address which is not implemented in the RAM ($0080 - $00FF) no ($0300-$0CFF, $0E00-$0FFF). The ILADR will generate the RST signal wh reset the CPU and other peripherals. If any other reset function is active at t of the ILADR reset signal, the RST signal will remain in the reset conditio the other reset condition(s) end. Notice that ILADR also forces the $\overline{RESET}$ p

SECTION 6
LOW POWER MODES

There are three modes of operation that reduce power consumption:

- Stop mode
- Wait mode
- Halt mode

The WAIT and STOP instructions provide two power saving modes by st various internal modules and/or the on-chip oscillator. The STOP and instructions are not normally used if the COP Watchdog Timer is enabled. A option is provided to convert the STOP instruction to a HALT, which is a WA instruction that does not halt the COP Watchdog Timer but has a recovery The flow of the STOP, HALT, and WAIT modes are shown in **Figure 6-1**.

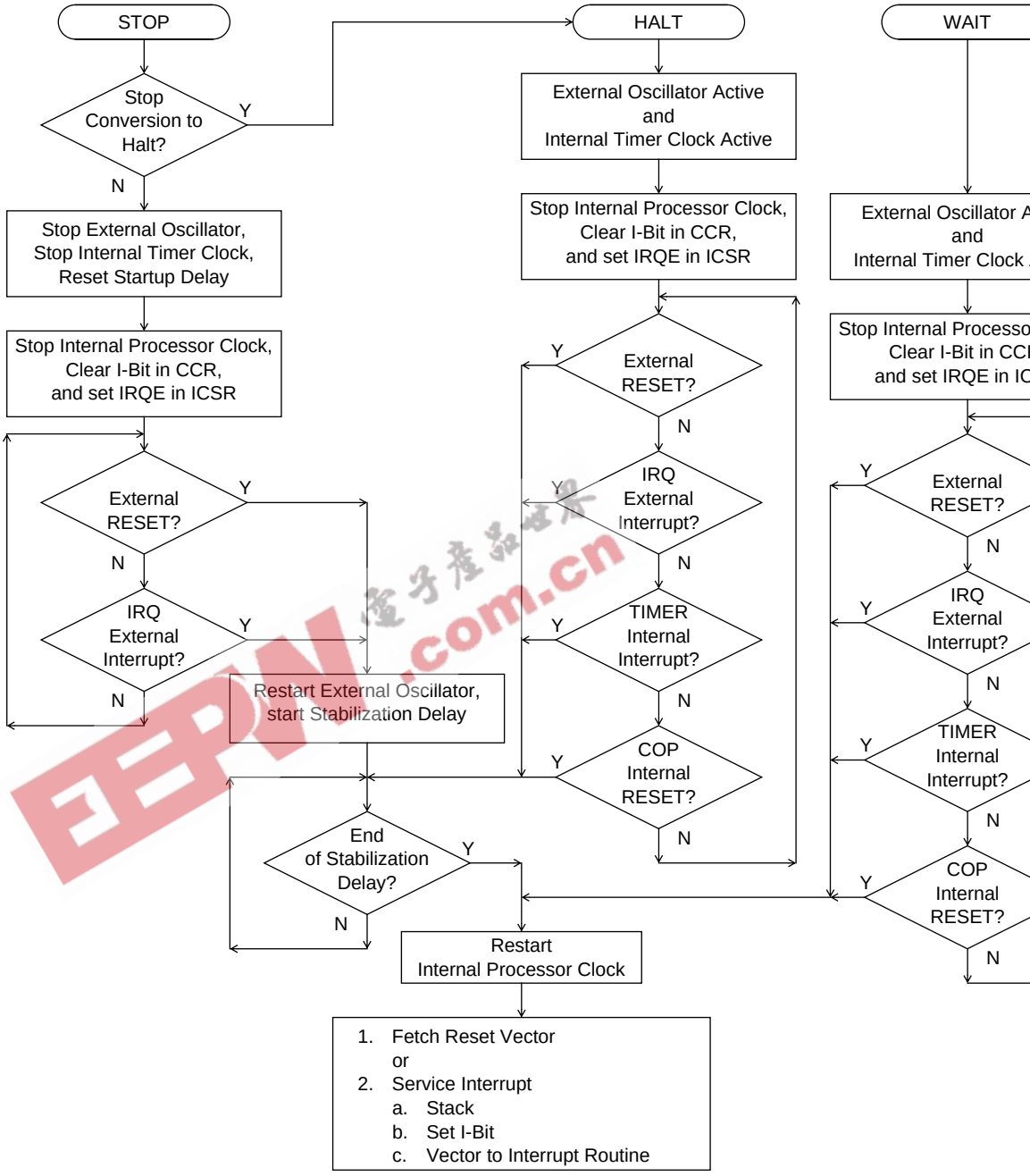


Figure 6-1. STOP/HALT/WAIT Flowcharts

6.1 STOP INSTRUCTION

The STOP instruction can result in one of two modes of operation depend
the STOP mask option chosen. One option is for the STOP instruction to o
like the STOP in normal MC68HC05 family members and place the device

STOP Mode. The other option is for the STOP instruction to behave like a instruction (except that the restart time will involve a delay) and place the de the HALT Mode.

6.1.1 STOP Mode

Execution of the STOP instruction in this mode (selected by a mask option) the MCU in its lowest power consumption mode. In the STOP Mode the i oscillator is turned off, halting all internal processing, including the COP Wa Timer.

When the CPU enters STOP Mode the interrupt flags (TOF and RTIF) a interrupt enable bits (TOFE and RTIE) in the TCSR are cleared by interna ware to remove any pending timer interrupt requests and to disable any timer interrupts. Execution of the STOP instruction automatically clears the the Condition Code Register and sets the IRQE enable bit in the IRQ Contr tus Register so that the IRQ external interrupt is enabled. All other reg including the other bits in the TCSR, and memory remain unaltered. All inp put lines remain unchanged.

The MCU can be brought out of the STOP Mode only by an IRQ external in or an externally generated RESET or an LVR reset. When exiting the STOP the internal oscillator will resume after a 224 or 4064 internal processor cycle oscillator stabilizing delay which is selected by a mask option.

NOTE

Execution of the STOP instruction with the STOP Mode Mask Option will the oscillator to stop and therefore disable the COP Watchdog Timer. If th Watchdog Timer is to be used, the STOP Mode should be changed to the Mode by choosing the appropriate mask option. See **Section 6.4** for more d

---

6.1.2 HALT Mode

Execution of the STOP instruction in this mode (selected by a mask option) the MCU in a low-power mode, which consumes more power than the Mode. In the HALT Mode the internal processor clock is halted, suspend processor and internal bus activity. Internal timer clocks remain active, per interrupts to be generated from the timer (MFT or Timer 1) or a reset to be ated from the COP Watchdog Timer. Execution of the STOP instruction aut cally clears the I-bit in the Condition Code Register and sets the IRQE ena in the IRQ Control/Status Register so that the IRQ external interrupt is en All other registers, memory, and input/output lines remain in their previous s

The HALT Mode may be terminated by a Timer interrupt, an external IRQ, a reset, or external $\overline{\text{RESET}}$ occurs. Since the internal timer is still running HALT mode, the wake up delay timer (oscillator stabilizing delay timer) ma counting from an unknown value. So, the internal processor clock will r

after a varied delay time which is from one to 224 or 4064 internal processo cycles (the POR delay time). The HALT Mode is not intended for normal u is provided to keep the COP Watchdog Timer active should the STOP inst opcode be inadvertently executed.

6.2 WAIT INSTRUCTION

The WAIT instruction places the MCU in a low-power mode, which con more power than the STOP Mode. In the WAIT Mode the internal processo is halted, suspending all processor and internal bus activity. Internal timer remain active, permitting interrupts to be generated from the timer or a rese generated from the COP Watchdog Timer. Execution of the WAIT instructio matically clears the I-bit in the Condition Code Register and sets the IRQE bit in the IRQ Control/Status Register so that the IRQ external interrupt is en All other registers, memory, and input/output lines remain in their previous s

If timer (MFT or Timer 1) interrupts are enabled, a TIMER interrupt will cau processor to exit the WAIT Mode and resume normal operation. The Timer r used to generate a periodic exit from the WAIT Mode. The WAIT Mode ma be exited when an external IRQ or an LVR reset or an external RESET occu

6.3 DATA-RETENTION MODE

If the LVR mask option is selected and since LVR kicks in whenever V_{DD} is the specified LVR trigger voltage which is higher than that required of th Retention mode, the Data Retention mode will not exist. Data Retention M only meaningful if LVR mask option is not selected.

The contents of RAM and CPU registers are retained at supply voltage as 2.0 VDC. This is called the data-retention mode where the data is held, b device is not guaranteed to operate. The $\overline{\text{RESET}}$ pin must be held low data-retention mode.

6.4 COP WATCHDOG TIMER CONSIDERATIONS

The COP Watchdog Timer is active in all modes of operation if enabled by a option. Thus, emulation of applications that do not service the COP should c done with devices that have the COP Mask Option disabled.

If the COP Watchdog Timer is selected by the mask option, any execution STOP instruction (either intentional or inadvertent due to the CPU beir turbed) will cause the oscillator to halt and prevent the COP Watchdog Time timing out unless the STOP to HALT conversion feature is enabled. Therefo recommended that the STOP instruction should be converted to a HALT i tion if the COP Watchdog Timer is enabled.

If the COP Watchdog Timer is selected by the mask option, the COP will re MCU when it times out. Therefore, it is recommended that the COP Wa should be disabled for a system that must have intentional uses of the WAIT for periods longer than the COP time-out period.

The recommended interactions and considerations for the COP Watchdog STOP instruction, and WAIT instruction are summarized in **Table 6-1**.

Table 6-1. COP Watchdog Timer Recommendations

IF the following conditions exist:		THEN the COP Watchdog Time should be as follows
STOP Instruction	WAIT Time	
converted to HALT by mask option	WAIT Time less than COP Time-Out	Enable or disable CO by mask option
converted to HALT by mask option	WAIT Time more than COP Time-Out	Disable COP by mask option
Acts as STOP	any length WAIT Time	Disable COP by mask option

SECTION 7
INPUT/OUTPUT PORTS

In the normal operating mode there are 14 usable bidirectional I/O lines arr
as one 8-bit I/O port (Port A), and one 6-bit I/O port (Port B). The individual
these ports are programmable as either inputs or outputs under software
by the data direction registers (DDR's). Also, if enabled by a single mask op
Port A and Port B I/O pins may have individual software programmable pul
or pull-up devices. Also, PA4-PA7 and PB1-PB2 pins have high current sink
bility; PA0-PA3 may function as additional $\overline{IRQ}$ interrupt input sources. No
both PA6 and PA7 pins have Schmitt trigger input for better noise immun
and V_{IL} specified at 2.4V and 0.8V, respectively.

The four port pins, PB2-PB5 are only available on the 20-pin version of the

7.1 SLOW OUTPUT FALLING-EDGE TRANSITION

		7	6	5	4	3	2	1	
DDRB $0005	R	SLOWE	0	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDI
	W								
reset⇒		0	0	0	0	0	0	0	

Figure 7-1. Port B Data Direction Register

SLOWE - Slow Transition Enable

The slow transition feature is controlled by the SLOWE bit of DDRB (
Data Direction Register).

1 = Enables the slow falling-edge output transition feature on the fo
O lines: PA6, PA7, PB1, and PB2. If the pin is configured as
output pin.

0 = Disables slow falling-edge output transition feature on the four
lines: PA6, PA7, PB1, and PB2. Default value of SLOWE b
cleared.

7.2 PORT A

Port A is a 8-bit bidirectional port which shares five of its pins with the IRQ
rupt system as shown in **Figure 7-2**. Note that both PA6 and PA7 pins
Schmitt trigger input for better noise immunity. Only the PA6 and PA7 pi
open-drained type with slow output transition feature.

Each Port A pin is controlled by the corresponding bits in a data direction re
a data register and a pulldown/up register. The Port A Data Register is loca
address $0000. The Port A Data Direction Register (DDRA) is located at a
$0004. The Port A Pulldown/up Register (PDURA) is located at address $
Reset operation will clear the DDRA and the PDURA. The Port A Data Reg
unaffected by reset.

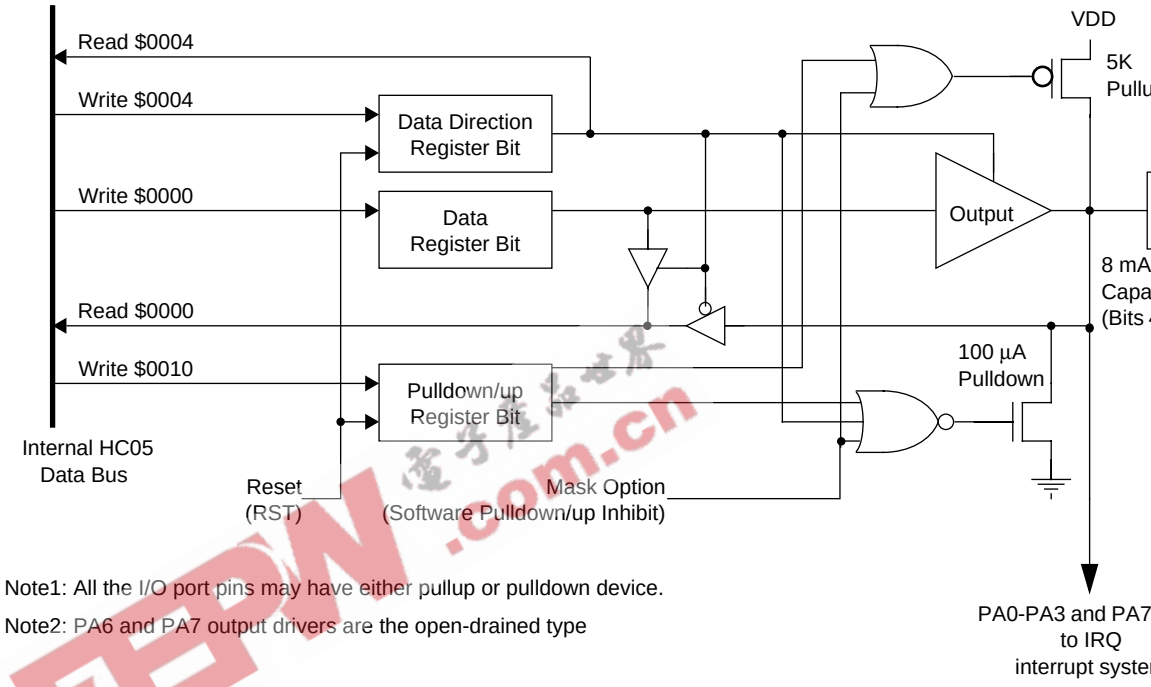


Figure 7-2. Port A I/O Circuitry

7.2.1 Port A Data Register

Each Port A I/O pin has a corresponding bit in the Port A Data Register. W
Port A pin is programmed as output, the corresponding data register bit
mines the logic state of that pin. When a Port A pin is programmed as inpu
read from the Port A Data Register will return the logic state of the corresp
I/O pin. The Port A data register is unaffected by reset.

7.2.2 Port A Data Direction Register

Each Port A I/O pin may be programmed as input by clearing the corresp
bit in the DDRA, or programmed as output by setting the corresponding bit
DDRA. The DDRA can be accessed at address $0004. The DDRA is clea
reset.

If configured as output pins, PA6 and PA7 have slow output falling-edge tra
feature. The slow transition feature is controlled by the SLOWE bit of
SLOWE bit, if set and if the pin is configured as an output pin, enables th
falling-edge output transition feature of all four I/O lines, PA6, PA7, PB1, an

7.2.3 Port A Pulldown/up Register

All Port A I/O pins may have software programmable pulldown/up devices e by the applicable mask option. If the pulldown/up mask option is selected, th down/up is activated whenever the corresponding bit in the PDURA is clea corresponding bit in the PDURA bit is set or the mask option for pulldown/up chosen, the pulldown/up will be disabled. A pulldown on an I/O pin is ac only if the I/O pin is programmed as an input whereas a pullup device on pin is always activated whenever enabled, regardless of port direction.

The PDURA is a write-only register. Any reads of location $0010 will return fined results. Since reset clears both the DDRA and the PDURA, all pins tialize as inputs with the pulldown active and pullup devices active (if enab mask option).

Typical value of port A pullup is 5KΩ.

7.2.4 Port A Drive Capability

The outputs for the upper four bits of Port A (PA4, PA5, PA6 and PA7) are c of sinking approximately 8mA of current to V_{SS}.

7.2.5 Port A I/O Pin Interrupts

The inputs to PA0, PA1, PA2, PA3 may be connected to the IRQ input of th if enabled by a mask option. The input to PA7 is also connected to the IRQ i the CPU, yet it is only enabled or disabled by software, not by mask optio interrupt capability is controlled by a set of control and status bits (IRQE1, I IRQR1), different from the set of control and status bits for that of PA0-PA $\overline{IRQ}$ pin (IRQE, IRQF, IRQR) in the same ICSR (Interrupt Control and Statu ister).

When connected as an alternate source of an IRQ interrupt, PA0-3 input p behave the same as the $\overline{IRQ}$ pin itself, except that their active state is a logic or a rising edge. The $\overline{IRQ}$ pin has an active state that is a logical zero or a edge. PA7 interrupt occurs, if enabled, only upon the falling edge at the inpu

If mask options for both level and edge sensitivity interrupts are chosen, the ence of a logic one or occurrence of a rising edge on any one of the low Port A pins will cause an IRQ interrupt request. If the edge-only sensit selected, the occurrence of a rising edge on any one of the lower four Port will cause an IRQ interrupt request. As long as any one of the lower four IRQ inputs remains at a logic one level, the other of the lower four Port inputs are effectively ignored.

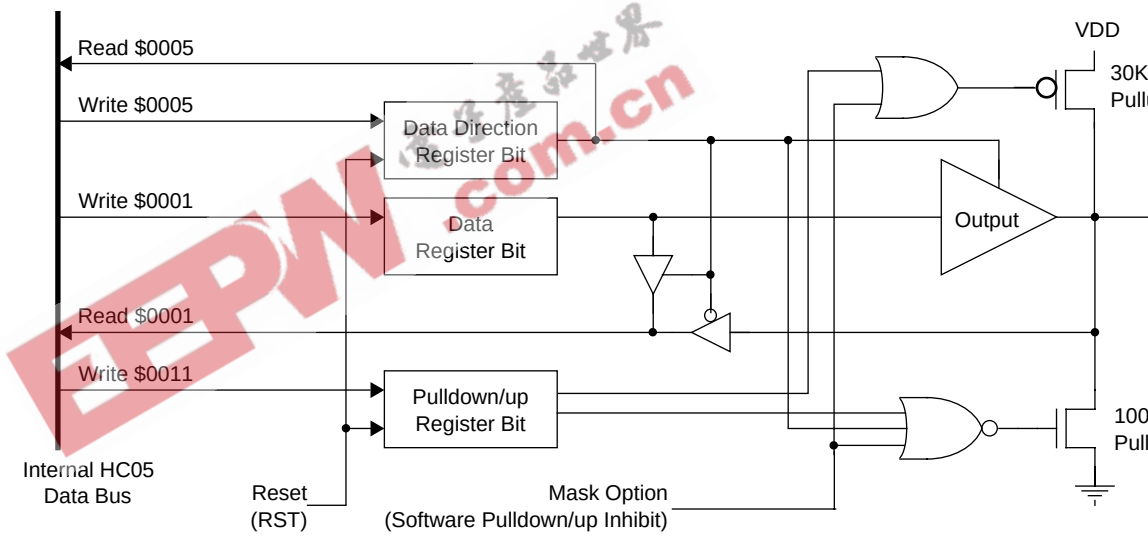
NOTE

The BIH and BIL instructions will only apply to the level on the $\overline{IRQ}$ pin itse not to the internal IRQ input to the CPU. Therefore BIH and BIL cannot be u test the state of the lower four Port A input pins as a group nor that of PA7.

7.3 PORT B

Port B is a 6-bit bidirectional port which functions as shown in **Figure 7-3** PB1 and PB2 are of open-drained type. Each Port B pin is controlled by the sponding bits in a data direction register, a data register and a pulldown/up ter. The Port B Data Register is located at address $0001. The Port B Direction Register (DDRB) is located at address $0005. The Port B Pulldo Register (PDURB) is located at address $0011. Reset clears the DDRB a PDURB. The Port B Data Register is unaffected by reset.

Please note that only PB0 and PB1 pins are bonded out in the 16-pin pa type. Actually, the PB1 and PB2 I/O port lines are short and bonded to the P the 16-pin package. Both PB1 and PB2 are of open-drained type, capable cally sinking 25mA current at V_{OL} 0.5V max. In order to constitute a sing capable of typically sinking 50mA, both PB1 and PB2 have to be written w same value at the same write cycle.



Note1: All the I/O port pins may have either pullup or pulldown device.

Note2: PB1 and PB2 output drivers are the open-drained type

Figure 7-3. Port B I/O Circuitry

Port Pin PB0 is shared with TCAP input of the 16-Timer input capture fu The input capture function can be programmed for a positive edge or the ne edge TCAP input. When an expected edge is generated on this pin, the c value at that moment will be captured into a capture register. For the details this feature please refer to the **Section 9**.

7.3.1 Port B Data Register

All Port B I/O pins have a corresponding bit in the Port B Data Register. W Port B pin is programmed as output the corresponding data regis determines the logic state of the output pin. When a Port B pin is programm input, any read from the Port B Data Register will return the logic state

corresponding I/O pin. The Port B data register is unaffected by reset. Unus
6 and 7 will always read as logic zeros, and any write to these bits will be ig
The Port B data register is unaffected by reset.

7.3.2 Port B Data Direction Register

Port B I/O pins may be programmed as an input by clearing the correspond
in the DDRB, or programmed as an output by setting the corresponding bit
DDRB. The DDRB can be accessed at address $0005. Unused bits 6 and
always read as logic zeros, and any write to these bits will be ignored.The
is cleared by reset.

If configured as output pins, PB1 and PB2 have slow output falling-edge tra
feature. The slow transition feature is controlled by the SLOWE bit of
SLOWE bit, if set and if the pin is configured as an output pin, enables th
falling-edge output transition feature of all four I/O lines, PA6, PA7, PB1 and

For the 16-pin package type, care should be taken in using PB1 pin, wi
bonded to two internal port B I/O lines PB1 and PB2, to constitute a 50mA
sinking driver. Both PB1 and PB2 I/O lines are capable of sinking 25mA.
are written with the same logic 0 value in the same write cycle, PB1 pin w
50 mA. If they are written with different values in the same write cycle, PB1
sink only 25mA.

For the 20-pin package type, I/O lines PB1 and PB2 are not bonded to the
pin. Hence, to constitute a 50mA current sinking driver, PB1 and PB2 pins h
be tied together externally and controlled in the same way as in the16-pin
age type case.

Also, if the slow transition feature of pin PB1 is enabled, a combination of I/
PB1 and PB2, is also a combination of slow transition features of I/O line
and PB2. PB2 line falling-edge output transition occurs $t_{CYC}/2$ after the
cycle, with a standard I/O edge transition time. Whereas for PB1 line, the
edge transition occurring immediately after the write cycle, but with an edg
sition time slower than standard I/Os, similar to PA6 and PA7 pins.

The net result is, for the 16-pin package type, since both PB1 and PB2 I/
are bonded to the same PB1 pin, the combination of delayed PB1 line sharp
output and the non-delayed slow transition output yields the desired slow
falling-edge transition.

For the 20-pin package, PB1 and PB2 pins should be tied externally to cr
driver with the desired slow output falling-edge transition feature. If SLOWE
and PB2 pin is not tied to PB1 pin, be advised that the output at PB2 ch
state $t_{CYC}/2$ after the write cycle.

7.3.3 Port B Pulldown/up Register

All Port B I/O pins may have software programmable pulldown/up devices e
by a mask option. If the pulldown/up mask option is selected, the pulldow
activated whenever the corresponding bit in the PDURB is clear. A pulldown

I/O pin is activated only if the I/O pin is programmed as an input whereas a device on an I/O pin is always activated whenever enabled, regardless direction.

The PDURB is a write-only register. Any reads of location $0011 will return fined results. Since reset clears both the DDRB and the PDURB, all pins tialize as inputs with the pulldown devices active and pullup devices ac chosen via mask option).

Typical value of port B pullup is 30KΩ.

7.4 I/O PORT PROGRAMMING

All I/O pins can be programmed as inputs or outputs, with or without pulldo devices.

7.4.1 Pin Data Direction

The direction of a pin is determined by the state of its corresponding bit associated port Data Direction Register (DDR). A pin is configured as an ou its corresponding DDR bit is set to a logic one. A pin is configured as an inp corresponding DDR bit is cleared to a logic zero.

The data direction bits DDRB0-DDRB5 and DDRA0-DDRA7 are read/wri which can be manipulated with read-modify-write instructions. At power reset, all DDRs are cleared which configures all port pins as inputs. If th down/up mask option is chosen, all pins will initially power-up with their so programmable pulldowns/ups enabled.

7.4.2 Output Pin

When an I/O pin is programmed as an output pin, the state of the corresp data register bit will determine the state of the pin. The state of the data r bits can be altered by writing to address $0000 for Port A and address $00 Port B. Reads of the corresponding data register bit at address $0000 or will return the state of the data register bit (not the state of the I/O pin Therefore bit manipulation is possible on all pins programmed as outputs.

If the corresponding bit in the pulldown/up register is clear (and the pulldo mask option is chosen), only output pins with pullups have an activated device connected to the pin. For those pins with pulldowns and configured a put pins, the pulldowns will be inactivated regardless of the state of the sponding pulldown/up register bit. Since the pulldown/up register bits are only, bit manipulation should not be used on these register bits.

7.4.3 Input Pin

When an I/O pin is programmed as an input pin, the state of the pin can be mined by reading the corresponding data register bit. Any writes to the sponding data register bit for an input pin will be ignored in the sense th written value will not be reflected on the pin, rather it is only reflected in th data register. Please refer to **Table 7-1** and **Table 7-2** for details.

If the corresponding bit in the pulldown/up register is clear (and the pulldo mask option is chosen) the input pin will also have an activated pulldo device. Since the pulldown/up register bits are write-only, bit manipulation not be used on these register bits.

7.4.4 I/O Pin Transitions

A "glitch" can be generated on an I/O pin when changing it from an input to a put unless the data register is first preconditioned to the desired state changing the corresponding DDR bit from a zero to a one.

If pulldowns are enabled by mask option, a floating input can be avoided by ing the pulldown/up register bit before changing the corresponding DDR one to a zero. This will insure that the pulldown device will be activated befo I/O pin changes from a driven output to a pulled low/high input.

7.4.5 I/O Pin Truth Tables

Every pin on Port A and Port B may be programmed as an input or an under software control as shown in **Table 7-1** and **Table 7-2**. All port I/O pir also have software programmable pulldown/up devices if selected by the ap ate mask option.

Table 7-1. Port A I/O Pin Functions

DDRA	I/O Pin Mode	Accesses to PDURA at $0010		Accesses to DDRA @ $0004	Accesses to Data Register @ $0000	
		Read	Write	Read/Write	Read	Write
0	IN, Hi-Z	U	PDURA0-7	DDRA0-7	I/O Pin	*
1	OUT	U	PDURA0-7	DDRA0-7	PA0-7	PA0-7

U is undefined

* Does not affect input, but stored to data register

Table 7-2. Port B I/O Pin Functions

DDRA	I/O Pin Mode	Accesses to PDURB at $0011		Accesses to DDRB @ $0005	Accesses to Data Register @ $0001	
		Read	Write	Read/Write	Read	Write
0	IN, Hi-Z	U	PDURB0-2	DDRB0-2	I/O Pin	*
1	OUT	U	PDURB0-2	DDRB0-2	PB0-5	PB0-5

U is undefined

* Does not affect input, but stored to data register

SECTION 8
MULTI-FUNCTION TIMER

The Multi-Function Timer module is a 15-stage ripple counter with Time
Flow (TOF), Real Time Interrupt (RTI), COP Watchdog, and the Power-On
delay function.

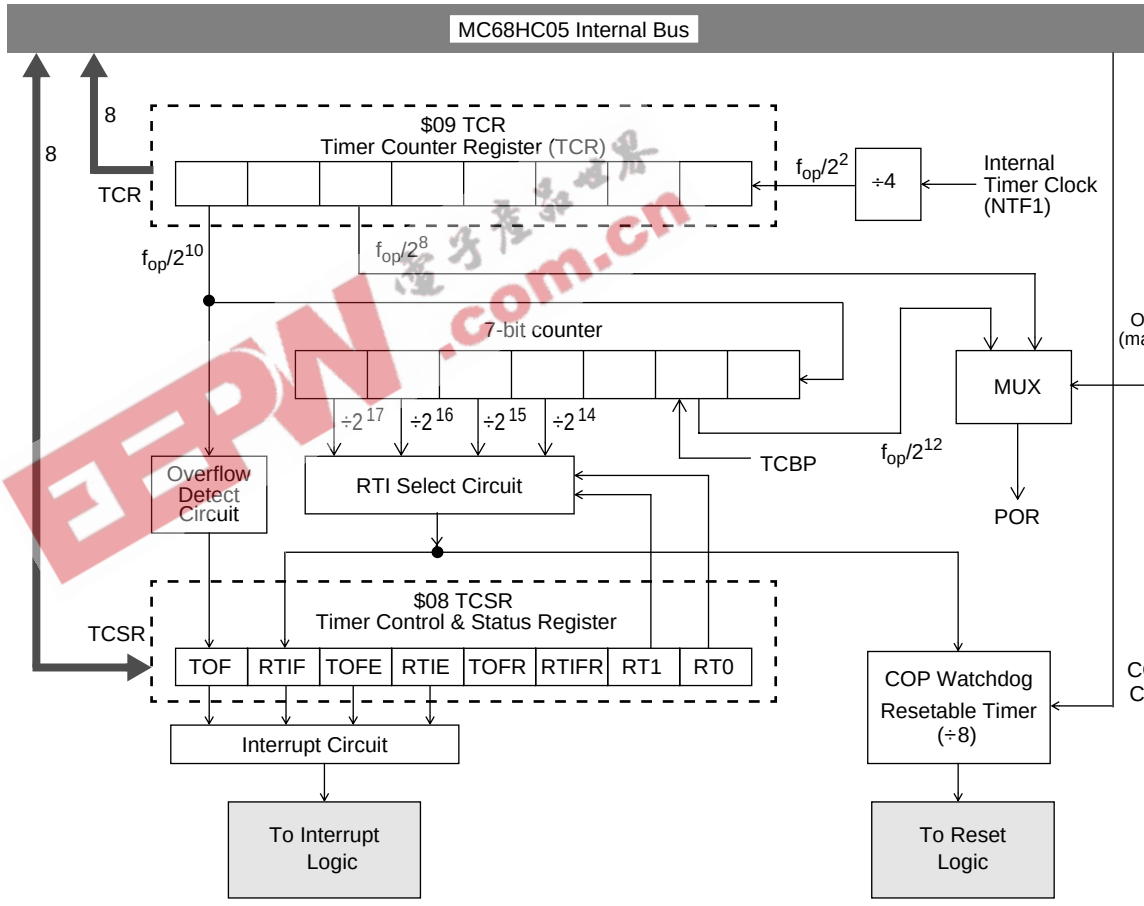


Figure 8-1. Multi-Function Timer Block Diagram

8.1 OVERVIEW

As shown in **Figure 8-1**, the Timer is driven by the timer clock, NTF1, divi four. NTF1 has the same phase and frequency as the processor bus clock but is not stopped by the WAIT or HALT Modes. This signal drives an 8-bit counter. The value of this 8-bit ripple counter can be read by the CPU at an by accessing the Timer Counter Register (TCR) at address $09. A timer ov function is implemented on the last stage of this counter, giving a possible rupt at the rate of f_{op}/1024. The POR function is generated at f_{op}/224 stag f_{op}/4064 stage, which is selected by a mask option.

The last stage of the 8-bit counter also drives a further 7-bit counter. The fir stages is used by the RTI circuit, giving possible RTI rates of $f_{OP}/2^{14}$, f_{O} $f_{OP}/2^{16}$ or $f_{OP}/2^{17}$, selected by RT1 and RT0 (see **Table 8-1**). The RTI rate tor bits, and the RTI and TOF enable bits and flags are located in the Time trol and Status Register at location $08.

The power-on cycle clears the entire counter chain and begins clockin counter. After 224 or 4064 cycles, the power-on reset circuit is released again clears the counter chain and allows the device to come out of reset. point, if $\overline{\text{RESET}}$ is not asserted, the timer will start counting up from zero an mal device operation will begin. If $\overline{\text{RESET}}$ is asserted at any time during ope the counter chain will be cleared.

8.2 COMPUTER OPERATING PROPERLY (COP) WATCHDOG

The COP Watchdog is enabled by a mask option.

The COP Watchdog Timer function is implemented by using the output of t circuit and further dividing it by eight. The minimum COP reset rates are lis **Table 8-1**. If the COP circuit times out, an internal reset is generated and th mal reset vector is fetched.

Preventing a COP time-out is done by writing a “0” to bit-0 of address $ When the COP is cleared, only the final divide by eight stage (output of the cleared.

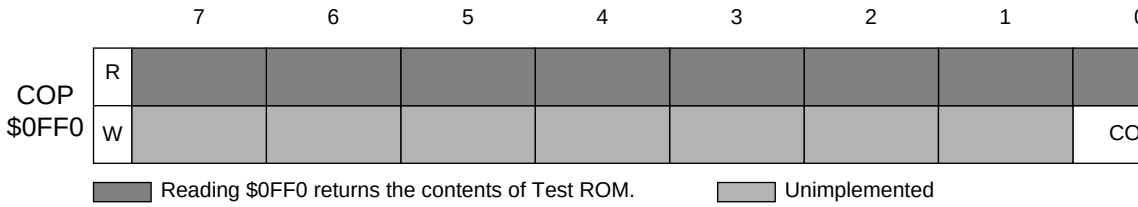


Figure 8-2. COP Watchdog Timer Location

8.3 MFT REGISTERS

The 15-stage Multi-function Timer contains two registers: a Timer Counter ter and a Timer Control/Status Register.

8.3.1 Timer Counter Register (TCR) $09

The Timer Counter Register is a read-only register which contains the c value of the 8-bit ripple counter at the beginning of the timer chain. This cou clocked at f_{op} divided by 4 and can be used for various functions including ware input capture. Extended time periods can be attained using the TOF fu to increment a temporary RAM storage location thereby simulating a 16- more) counter. The value of each bit of the TCR is shown in **Figure 8-3**. Th ister is cleared by reset.

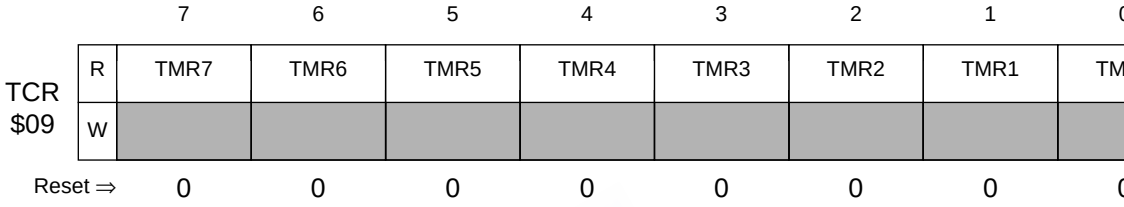


Figure 8-3. Timer Counter Register

8.3.2 Timer Control/Status Register (TCSR) $08

The TCSR contains the timer interrupt flag bits, the timer interrupt enable bi the real time interrupt rate select bits. Bit 2 and bit 3 are write-only bits wh read as logical zeros. **Figure 8-4** shows the value of each bit in the TCSR ing reset.

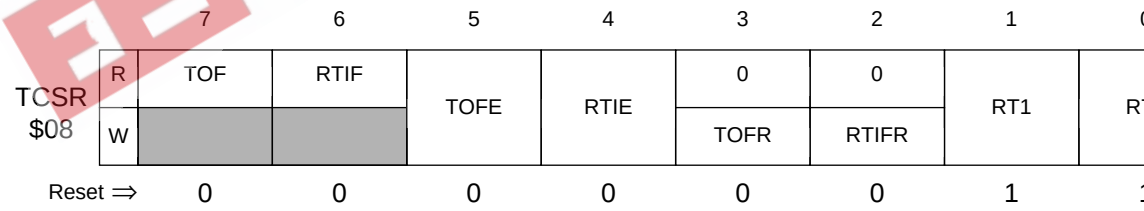


Figure 8-4. Timer Control/Status Register (TCSR)

TOF - Timer Overflow Flag

The TOF is a read-only flag bit.

1 = Set when the 8-bit ripple counter rolls over from $FF to $00 TIMER Interrupt request will be generated if TOFE is also set.

0 = Reset by writing a logical one to the TOF acknowledge bit, TO Writing to the TOF flag bit has no effect on its value. This b cleared by reset.

RTIF - Real Time Interrupt Flag

The RTIF is a read-only flag bit.

1 = Set when the output of the chosen (1 of 4 selections) Real T Interrupt stage goes active. A TIMER Interrupt request will generated if RTIE is also set.

0 = Reset by writing a logical one to the RTIF acknowledge bit, RTI Writing to the RTIF flag bit has no effect on its value. This b cleared by reset.

TOFE - Timer Overflow Enable

The TOFE is an enable bit that allows generation of a TIMER Interrup overflow of the Timer Counter Register.

1 = When set, the TIMER Interrupt is generated when the TOF flag b set.

0 = When cleared, no TIMER interrupt caused by TOF bit set wil generated. This bit is cleared by reset.

RTIE - Real Time Interrupt Enable

The RTIE is an enable bit that allows generation of a TIMER Interrupt RTIF bit.

1 = When set, the TIMER Interrupt is generated when the RTIF flag b set.

0 = When cleared, no TIMER interrupt caused by RTIF bit set wil generated. This bit is cleared by reset.

TOFR - Timer Overflow Acknowledge

The TOFR is an acknowledge bit that resets the TOF flag bit. This bit is fected by reset. Reading the TOFR will always return a logical zero.

1 = Clears the TOF flag bit.

0 = Does not clear the TOF flag bit.

RTIFR - Real Time Interrupt Acknowledge

The RTIFR is an acknowledge bit that resets the RTIF flag bit. This bit is fected by reset. Reading the RTIFR will always return a logical zero.

1 = Clears the RTIF flag bit.

0 = Does not clear the RTIF flag bit.

RT1, RT0 - Real Time Interrupt Rate Select

The RT0 and RT1 control bits select one of four taps for the Real Time In circuit. **Table 8-1** shows the available interrupt rates for two f_{op} values. Be RT0 and RT1 control bits are set by reset, selecting the lowest periodic ra therefore the maximum time in which to alter these bits if necessary should be taken when altering RT0 and RT1 if the time-out period is imi or uncertain. If the selected tap is modified during a cycle in which the c is switching, an RTIF could be missed or an additional one could be gene To avoid problems, the COP should be cleared just prior to changing RTI

Table 8-1. RTI Rates and COP Reset Times

RT1	RT0	RTI Rates at f_{OP} Freq. specified:			Min. COP Reset at f_{OP} Freq. speci		
		Divider	1MHz	2MHz	Divider	1MHz	2M
0	0	16384	16.384ms	8.192ms	131072	131ms	66
0	1	32768	32.768ms	16.384ms	262144	262ms	131
1	0	65536	65.536ms	32.768ms	524288	524ms	262
1	1	131072	131.072ms	65.536ms	1048576	1059ms	524

8.4 OPERATION DURING STOP MODE

The timer system is cleared when going into STOP mode. When STOP is by an external interrupt or an LVR reset or an external $\overline{\text{RESET}}$, the internal c tor will resume, followed by a 224 (or 4064) internal processor oscillator stal delay. The timer system counter is then cleared and operation resumes. If c by a mask option, the STOP instruction will initiate HALT mode and the effe the timer are as described in **Section 8.5**.

8.5 OPERATION DURING WAIT/HALT MODE

The CPU clock halts during the WAIT/HALT mode, but the timer remains ac interrupts are enabled, a timer interrupt or custom periodic interrupt will cau processor to exit the WAIT/HALT mode.

SECTION 9
16-BIT TIMER

This 16-bit Timer (Timer1) is a Programmable Timer with an Input C function. **Figure 9-1** shows a block diagram of the 16-bit programmable tim

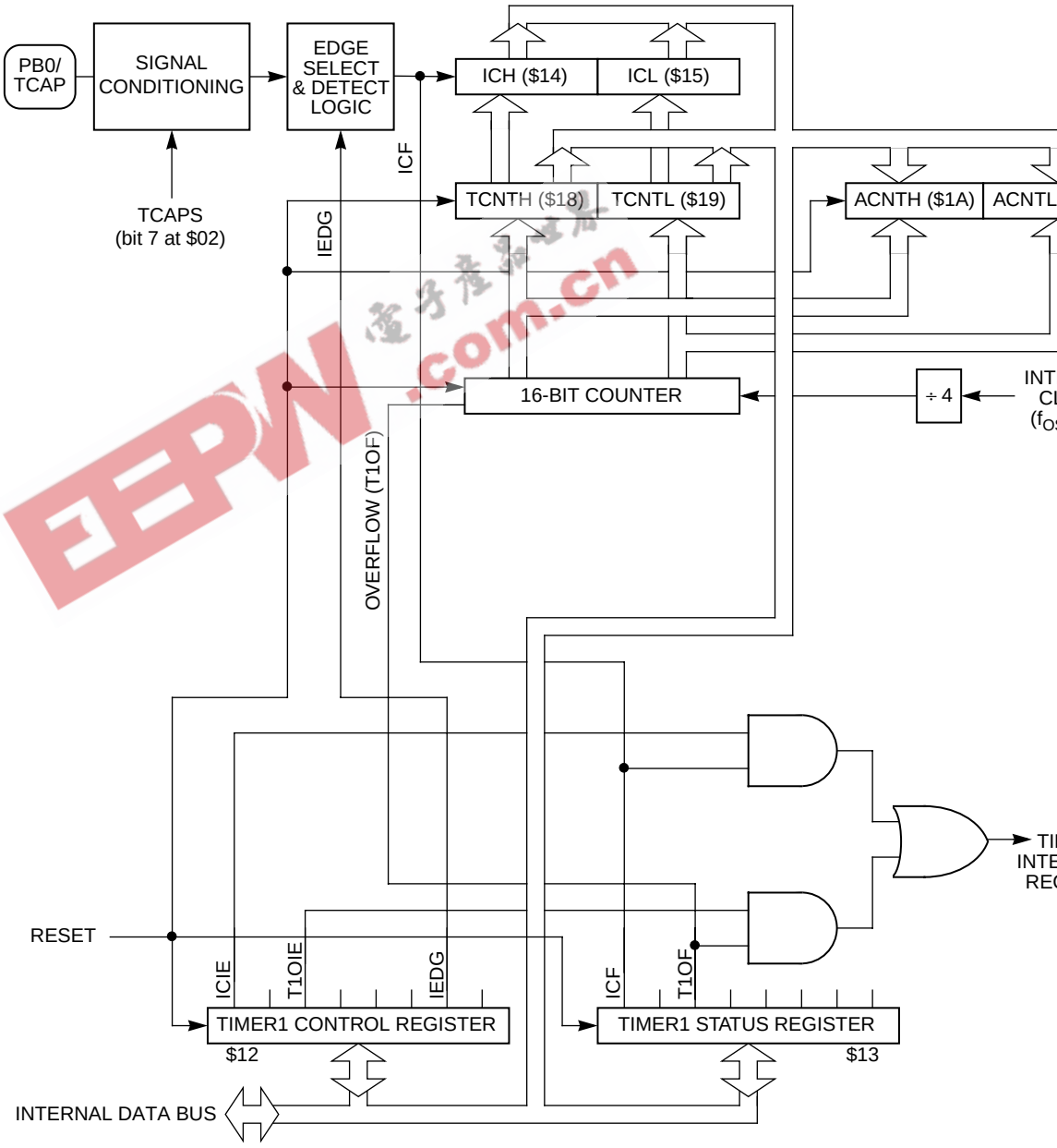


Figure 9-1. 16-Bit Timer Block Diagram

The basis of the 16-bit Timer is a 16-bit free-running counter which increa count with each internal bus clock cycle. The counter is the timing referer the input capture and output compare functions. The input capture and compare functions provide a means to latch the times at which external occur, to measure input waveforms, and to generate output waveforms and delays. Software can read the value in the 16-bit free-running counter at ar without affect the counter sequence.

Because of the 16-bit timer architecture, the I/O registers are pairs of 8-bit ters. Each register pair contains the high and low byte of that function. Ger accessing the low byte of a specific timer function allows full control of tha tion; however, an access of the high byte inhibits that specific timer functio the low byte is also accessed.

Because the counter is 16 bits long and preceded by a fixed divide-by-fou caler, the counter rolls over every 262,144 internal clock cycles. Timer res with a 4MHz crystal oscillator is 2 microsecond/count.

The interrupt capability and the input capture edge are controlled by the time trol register (T1CR) located at $0012 and the status of the interrupt flags read from the timer status register (T1SR) located at $0013.

9.1 TIMER1 COUNTER REGISTERS (TCNTH, TCNTL)

The functional block diagram of the 16-bit free-running timer counter and registers is shown in **Figure 9-2**. The timer registers include a transparent latch on the LSB of the 16-bit timer counter.

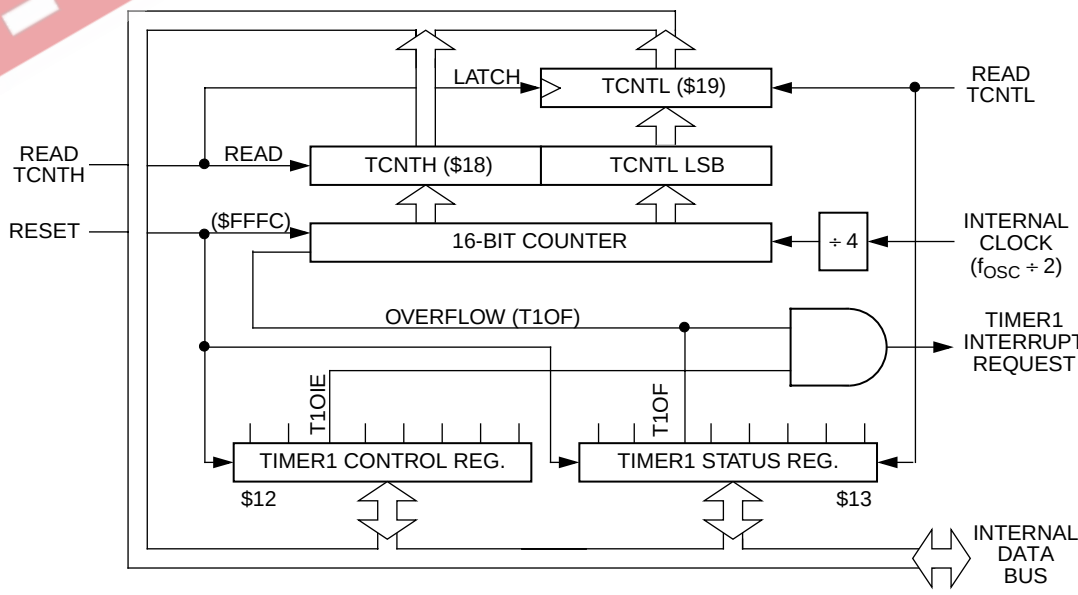


Figure 9-2. 16-Bit Timer Counter Block Diagram

The timer counter registers (TCNTH, TCNTL) shown in **Figure 9-3** are rea
locations which contain the current high and low bytes of the 16-bit free-r
counter. Writing to the timer registers has no effect. Reset of the device p
the timer counter to $FFFC.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
TCNTH	R	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9
$0018	W							
reset:		1	1	1	1	1	1	1
TCNTL	R	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1
$0019	W							
reset:		1	1	1	1	1	1	0

Figure 9-3. 16-Bit Timer Counter Registers (TCNTH, TCNTL)

The TCNTL latch is a transparent read of the LSB until the a read of the T
takes place. A read of the TCNTH latches the LSB into the TCNTL locatio
the TCNTL is again read. The latched value remains fixed even if multiple re
the TCNTH take place before the next read of the TCNTL. Therefore, when
ing the MSB of the timer at TCNTH the LSB of the timer at TCNTL must a
read to complete the read sequence.

During power-on-reset (POR), the counter is initialized to $FFFC and
counting after the oscillator start-up delay. Because the counter is 16 bits ar
ceded by a fixed divide-by-four prescaler, the value in the counter repeats
262, 144 internal bus clock cycles (524, 288 oscillator cycles).

When the free-running counter rolls over from $FFFF to $0000, the timer ov
flag bit (T1OF) is set in the T1SR. When the T1OF is set, it can generate an
rupt if the timer overflow interrupt enable bit (T1OIE) is also set in the T1C
T1OF flag bit can only be reset by reading the TCNTL after reading the T1S

Other than clearing any possible T1OF flags, reading the TCNTH and TC
any order or any number of times does not have any effect on the 16-bit fre
ning counter.

NOTE

To prevent interrupts from occurring between readings of the TCNTH and T
set the I bit in the condition code register (CCR) before reading TCNTH and
the I bit after reading TCNTL.

9.2 ALTERNATE COUNTER REGISTERS (ACNTH, ACNTL)

The functional block diagram of the 16-bit free-running timer counter and alt
counter registers is shown in **Figure 9-4**. The alternate counter registers b
the same as the timer counter registers, except that any reads of the alt

counter will not have any effect on the T1OF flag bit and Timer interrupt alternate counter registers include a transparent buffer latch on the LSB of t bit timer counter.

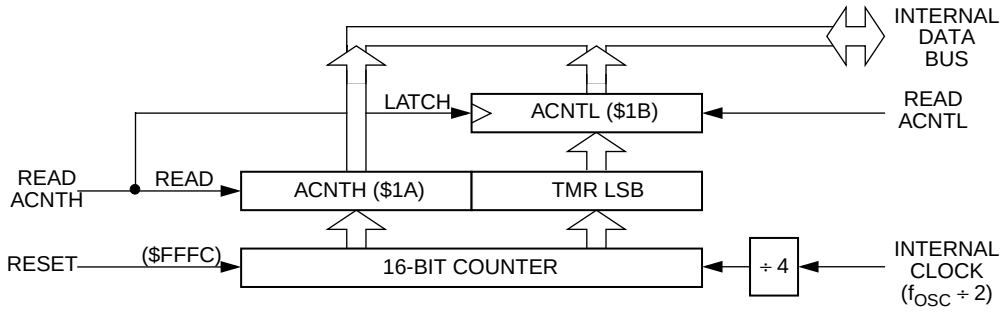


Figure 9-4. Alternate Counter Block Diagram

The alternate counter registers (ACNTH, ACNTL) shown in **Figure 9-5** are only locations which contain the current high and low bytes of the 16-bit fre ning counter. Writing to the alternate counter registers has no effect. Reset device presets the timer counter to $FFFC.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
ACNTH	R	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9
$001A	W							
reset:		1	1	1	1	1	1	1
ACNTL	R	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1
$001B	W							
reset:		1	1	1	1	1	1	0

Figure 9-5. Alternate Counter Registers (ACNTH, ACNTL)

The ACNTL latch is a transparent read of the LSB until the a read of the A takes place. A read of the ACNTH latches the LSB into the ACNTL locatio the ACNTL is again read. The latched value remains fixed even if multiple re the ACNTH take place before the next read of the ACNTL. Therefore, when ing the MSB of the timer at ACNTH the LSB of the timer at ACNTL must a read to complete the read sequence.

During power-on-reset (POR), the counter is initialized to $FFFC and counting after the oscillator start-up delay. Because the counter is 16 bits ar ceded by a fixed divide-by-four prescaler, the value in the counter repeats 262,144 internal bus clock cycles (524,288 oscillator cycles).

Reading the ACNTH and ACNTL in any order or any number of times do have any effect on the 16-bit free-running counter or the T1OF flag bit.

NOTE

To prevent interrupts from occurring between readings of the ACNTH and A set the I bit in the condition code register (CCR) before reading ACNTH an the I bit after reading ACNTL.

9.3 INPUT CAPTURE REGISTERS

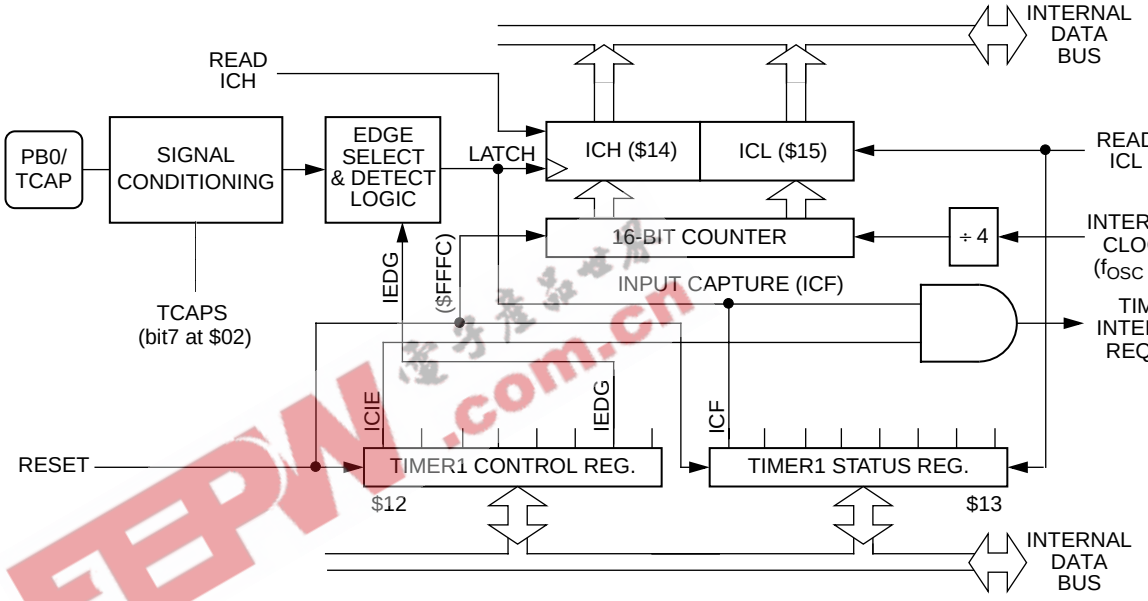


Figure 9-6. Timer Input Capture Block Diagram

The input capture function is a technique whereby an external signal (con to PB0/TCAP pin) is used to trigger the 16-bit timer counter. In this way it is ble to relate the timing of an external signal to the internal counter valu hence to elapsed time.

NOTE

Since the TCAP pin is shared with the PB0 I/O pin, changing the state of th DDR or Data Register can cause an unwanted TCAP interrupt. This c avoided by clearing the ICIE bit before changing the configuration of PB clearing any pending interrupts before enabling ICIE.

The signal on the TCAP pin is first directed to a schmitt trigger or a v comparator as shown in **Figure 9-8**. Setting the TCAPS bit to “1” will enal comparator and the $V_{DD}/2$ reference voltage.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
T1CC	R	TCAPS						
$0002	W							
reset:		0	0	0	0	0	0	0

Figure 9-7. Timer1 Capture Control Register

TCAPS — Timer Input Capture Comparator Enable

1 = Timer input capture comparator is selected.
0 = Timer input capture comparator schmitt trigger is selected.

NOTE

When the comparator and $V_{DD}/2$ reference are enabled, PB0 pin will automa
becomes an input pin, irrespective of DDR setting. However, it is recommen
set PB0 as an input first (via DDR), before enabling the comparator. A read
will reflect the TCAP pin status, not the PB0 register bit.

The comparator uses the $V_{DD}/2$ reference as the compare voltage, resultin
typical output as shown in **Figure 9-9**.

Switching off the $V_{DD}/2$ voltage reference by clearing TCAPS=0 will furthe
power when the MCU is in a low power mode.

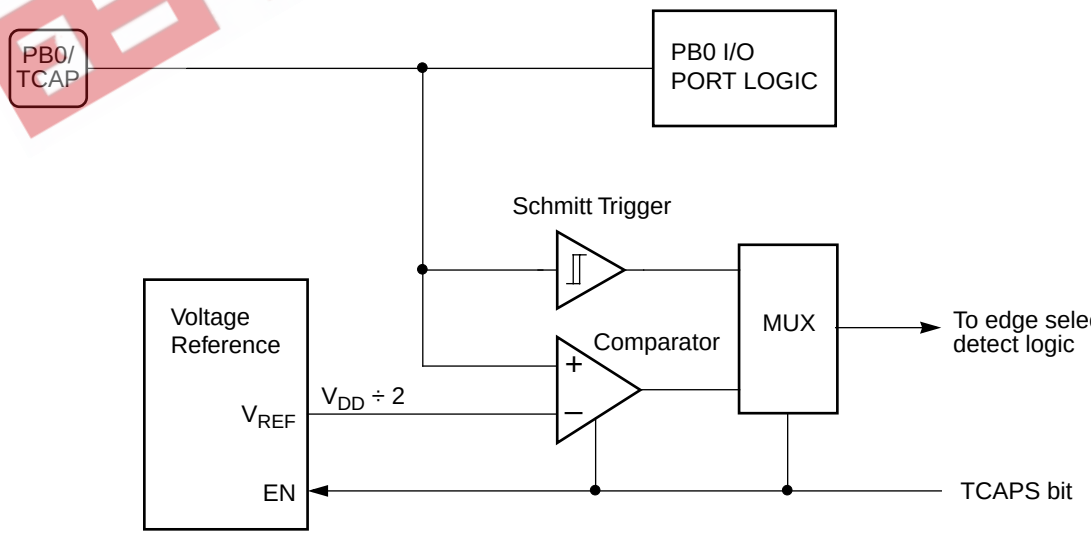


Figure 9-8. TCAP Input Signal Conditioning

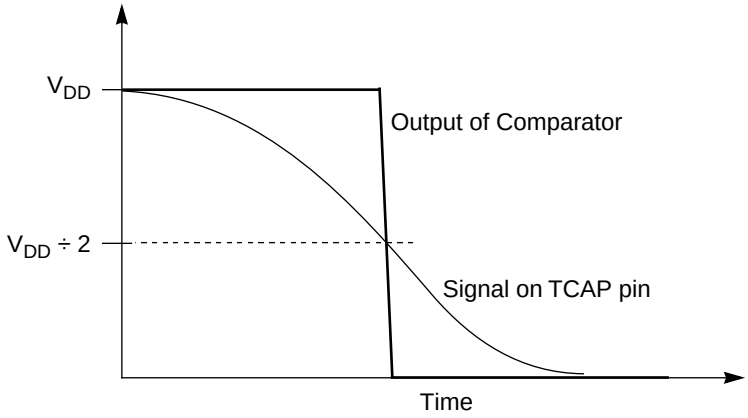


Figure 9-9. TCAP Input Comparator Output

When the input capture circuitry detects an active edge on the TCAP latches the contents of the free-running timer counter registers into the inpu ture registers as shown in **Figure 9-6**.

Latching values into the input capture registers at successive edges of the polarity measures the period of the selected input signal. Latching the count ues at successive edges of opposite polarity measures the pulse width of t nal.

The input capture registers are made up of two 8-bit read-only registers (ICH as shown in **Figure 9-10**. The input capture edge detector contains a Schm ger to improve noise immunity. The edge that triggers the counter tran defined by the input edge bit (IEDG) in the T1CR. Reset does not affect th tents of the input capture registers.

The result obtained by an input capture will be one count higher than the va the free-running timer counter preceding the external transition. This de required for internal synchronization. Resolution is affected by the pre allowing the free-running timer counter to increment once every four interna cycles (eight oscillator clock cycles).

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
ICH	R	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9
$0014	W							
reset:		U	U	U	U	U	U	U

ICL	R	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1
$0015	W							
reset:		U	U	U	U	U	U	U

U = UNAFFECTED BY RESET

Figure 9-10. Input Capture Registers (ICH, ICL)

Reading the ICH inhibits further captures until the ICL is also read. Readi
ICL after reading the timer status register (T1SR) clears the ICF flag bit. do
inhibit transfer of the free-running counter. There is no conflict between r
the ICL and transfers from the free-running timer counters. The input captu
isters always contain the free-running timer counter value which correspo
the most recent input capture.

NOTE

To prevent interrupts from occurring between readings of the ICH and ICL, s
I bit in the condition code register (CCR) before reading ICH and clear th
after reading ICL.

9.4 TIMER1 CONTROL REGISTER (T1CR)

The timer control register is shown in **Figure 9-11** performs the following
tions:

- Enables input capture interrupts
- Enables output compare interrupts
- Enables timer overflow interrupts
- Control the active edge polarity of the TCAP signal on pin PB0/TCAP

Reset clears all the bits in the T1CR with the exception of the IEDG bit w
unaffected.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	
T1CR	R	ICIE	0	T1OIE	0	0	0	IEDG	
$0012	W								
reset:		0	0	0	0	0	0	U	

U = UNAFFECTED BY RESET

Figure 9-11. Timer Control Register (T1CR)

ICIE - INPUT CAPTURE INTERRUPT ENABLE

This read/write bit enables interrupts caused by an active signal on the
TCAP pin. Reset clears the ICIE bit.

1 = Input capture interrupts enabled.
0 = Input capture interrupts disabled.

T1OIE - TIMER OVERFLOW INTERRUPT ENABLE

This read/write bit enables interrupts caused by a timer1 overflow. Reset
the T1OIE bit.

1 = Timer1 overflow interrupts enabled.
0 = Timer1 overflow interrupts disabled.

IEDG - INPUT CAPTURE EDGE SELECT

The state of this read/write bit determines whether a positive or negative tion on the TCAP pin triggers a transfer of the contents of the timer regi the input capture register. Reset has no effect on the IEDG bit.

1 = Positive edge (low to high transition) triggers input capture.
0 = Negative edge (high to low transition) triggers input capture.

9.5 TIMER1 STATUS REGISTER (T1SR)

The timer status register (T1SR) shown in **Figure 9-12** contains flags for t lowing events:

- An active signal on the PB0/TCAP pin, transferring the contents of timer registers to the input capture registers.
- An overflow of the timer registers from $FFFF to $0000.

Writing to any of the bits in the T1SR has no effect. Reset does not chan state of any of the flag bits in the T1SR.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
T1SR	R	ICF	0	T1OF	0	0	0	0
$0013	W							
reset:		U	U	U	0	0	0	0

U = UNAFFECTED BY RESET

Figure 9-12. Timer Status Registers (T1SR)

ICF - INPUT CAPTURE FLAG

The ICF bit is automatically set when an edge of the selected polarity occ the PB0/TCAP pin. Clear the ICF bit by reading the timer status regist the ICF set, and then reading the low byte (ICL, $0015) of the input c registers. Reset has no effect on ICF.

T1OF - TIMER1 OVERFLOW FLAG

The T1OF bit is automatically set when the 16-bit timer counter rolls ove $FFFF to $0000. Clear the T1OF bit by reading the timer status regist the T1OF set, and then accessing the low byte (TCNTL, $0019) of the registers. Reset has no effect on T1OF.

9.6 TIMER1 OPERATION DURING WAIT MODE

During WAIT mode the 16-bit timer continues to operate normally and may ate an interrupt to trigger the MCU out of the WAIT mode.

9.7 TIMER1 OPERATION DURING STOP MODE

When the MCU enters the STOP mode the free-running counter stops co (the internal processor clock is stopped). It remains at that particular coun until the STOP mode is exited by applying a low signal to the $\overline{IRQ}$ pin, at

time the counter resumes from its stopped value as if nothing had happe
STOP mode is exited via an external reset (logic low applied to the RESE
the counter is forced to $FFFC.

If a valid input capture edge occurs at the PB0/TCAP pin during the STOP
the input capture detect circuitry will be armed. This action does not set an
or “wake up” the MCU, but when the MCU does “wake up” there will be an
input capture flag (and data) from the first valid edge. If the STOP mode is
by an external reset, no input capture flag or data will be present even if
input capture edge was detected during the STOP mode.

SECTION 10
INSTRUCTION SET

This section describes the addressing modes and instruction types.

10.1 ADDRESSING MODES

The CPU uses eight addressing modes for flexibility in accessing data addressing modes define the manner in which the CPU finds the data requ execute an instruction. The eight addressing modes are the following:

- Inherent
- Immediate
- Direct
- Extended
- Indexed, No Offset
- Indexed, 8-Bit Offset
- Indexed, 16-Bit Offset
- Relative

10.1.1 Inherent

Inherent instructions are those that have no operand, such as return from in (RTI) and stop (STOP). Some of the inherent instructions act on data in th registers, such as set carry flag (SEC) and increment accumulator (Inherent instructions require no memory address and are one byte long.

10.1.2 Immediate

Immediate instructions are those that contain a value to be used in an op with the value in the accumulator or index register. Immediate instructions no memory address and are two bytes long. The opcode is the first byte, a immediate data value is the second byte.

10.1.3 Direct

Direct instructions can access any of the first 256 memory addresses wi
bytes. The first byte is the opcode, and the second is the low byte of the op
address. In direct addressing, the CPU automatically uses $00 as the high
the operand address. BRSET and BRCLR are three-byte instructions th
direct addressing to access the operand and relative addressing to spe
branch destination.

10.1.4 Extended

Extended instructions use only three bytes to access any address in memo
first byte is the opcode; the second and third bytes are the high and low by
the operand address.

When using the Motorola assembler, the programmer does not need to s
whether an instruction is direct or extended. The assembler automatically s
the shortest form of the instruction.

10.1.5 Indexed, No Offset

Indexed instructions with no offset are one-byte instructions that can acces
with variable addresses within the first 256 memory locations. The index r
contains the low byte of the conditional address of the operand. The
automatically uses $00 as the high byte, so these instructions can a
locations $0000–$00FF.

Indexed, no offset instructions are often used to move a pointer through a ta
to hold the address of a frequently used RAM or I/O location.

10.1.6 Indexed, 8-Bit Offset

Indexed, 8-bit offset instructions are two-byte instructions that can acces
with variable addresses within the first 511 memory locations. The CPU ad
unsigned byte in the index register to the unsigned byte following the opcod
sum is the conditional address of the operand. These instructions can a
locations $0000–$01FE.

Indexed 8-bit offset instructions are useful for selecting the kth element
n-element table. The table can begin anywhere within the first 256 m
locations and could extend as far as location 510 ($01FE). The k value is ty
in the index register, and the address of the beginning of the table is in th
following the opcode.

10.1.7 Indexed, 16-Bit Offset

Indexed, 16-bit offset instructions are three-byte instructions that can acces with variable addresses at any location in memory. The CPU adds the un byte in the index register to the two unsigned bytes following the opcode. Th is the conditional address of the operand. The first byte after the opcode high byte of the 16-bit offset; the second byte is the low byte of the offset. instructions can address any location in memory.

Indexed, 16-bit offset instructions are useful for selecting the kth elemen n-element table anywhere in memory.

As with direct and extended addressing, the Motorola assembler determin shortest form of indexed addressing.

10.1.8 Relative

Relative addressing is only for branch instructions. If the branch condition i the CPU finds the conditional branch destination by adding the signe following the opcode to the contents of the program counter. If the condition is not true, the CPU goes to the next instruction. The offset is a s two's complement byte that gives a branching range of –128 to +127 byte the address of the next location after the branch instruction.

When using the Motorola assembler, the programmer does not need to ca the offset, because the assembler determines the proper offset and verifies is within the span of the branch.

10.1.9 Instruction Types

The MCU instructions fall into the following five categories:

- Register/Memory Instructions
- Read-Modify-Write Instructions
- Jump/Branch Instructions
- Bit Manipulation Instructions
- Control Instructions

10.1.10 Register/Memory Instructions

Most of these instructions use two operands. One operand is in eith
accumulator or the index register. The CPU finds the other operand in m
Table 10-1 lists the register/memory instructions.

Table 10-1. Register/Memory Instructions

Instruction	Mnemonic
Add Memory Byte and Carry Bit to Accumulator	ADC
Add Memory Byte to Accumulator	ADD
AND Memory Byte with Accumulator	AND
Bit Test Accumulator	BIT
Compare Accumulator	CMP
Compare Index Register with Memory Byte	CPX
EXCLUSIVE OR Accumulator with Memory Byte	EOR
Load Accumulator with Memory Byte	LDA
Load Index Register with Memory Byte	LDX
Multiply	MUL
OR Accumulator with Memory Byte	ORA
Subtract Memory Byte and Carry Bit from Accumulator	SBC
Store Accumulator in Memory	STA
Store Index Register in Memory	STX
Subtract Memory Byte from Accumulator	SUB

10.1.11 Read-Modify-Write Instructions

These instructions read a memory location or a register, modify its content write the modified value back to the memory location or to the register. The negative or zero instruction (TST) is an exception to the read-modif sequence because it does not write a replacement value. **Table 10-2** lis read-modify-write instructions.

Table 10-2. Read-Modify-Write Instructions

Instruction	Mnemonic
Arithmetic Shift Left	ASL
Arithmetic Shift Right	ASR
Clear Bit in Memory	BCLR
Set Bit in Memory	BSET
Clear	CLR
Complement (One's Complement)	COM
Decrement	DEC
Increment	INC
Logical Shift Left	LSL
Logical Shift Right	LSR
Negate (Two's Complement)	NEG
Rotate Left through Carry Bit	ROL
Rotate Right through Carry Bit	ROR
Test for Negative or Zero	TST

10.1.12 Jump/Branch Instructions

Jump instructions allow the CPU to interrupt the normal sequence of the pr counter. The unconditional jump instruction (JMP) and the jump to subr instruction (JSR) have no register operand. Branch instructions allow the C interrupt the normal sequence of the program counter when a test cond met. If the test condition is not met, the branch is not performed. All b instructions use relative addressing.

Bit test and branch instructions cause a branch based on the state readable bit in the first 256 memory locations. These three-byte instructions combination of direct addressing and relative addressing. The direct addr the byte to be tested is in the byte following the opcode. The third byte signed offset byte. The CPU finds the conditional branch destination by add

third byte to the program counter if the specified bit tests true. The bit to be
and its condition (set or clear) is part of the opcode. The span of branching
–128 to +127 from the address of the next location after the branch instr
The CPU also transfers the tested bit to the carry/borrow bit of the conditio
register. **Table 10-3** lists the jump and branch instructions.

Table 10-3. Jump and Branch Instructions

Instruction	Mnemonic
Branch if Carry Bit Clear	BCC
Branch if Carry Bit Set	BCS
Branch if Equal	BEQ
Branch if Half-Carry Bit Clear	BHCC
Branch if Half-Carry Bit Set	BHCS
Branch if Higher	BHI
Branch if Higher or Same	BHS
Branch if $\overline{\text{IRQ}}$ Pin High	BIH
Branch if $\overline{\text{IRQ}}$ Pin Low	BIL
Branch if Lower	BLO
Branch if Lower or Same	BLS
Branch if Interrupt Mask Clear	BMC
Branch if Minus	BMI
Branch if Interrupt Mask Set	BMS
Branch if Not Equal	BNE
Branch if Plus	BPL
Branch Always	BRA
Branch if Bit Clear	BRCLR
Branch Never	BRN
Branch if Bit Set	BRSET
Branch to Subroutine	BSR
Unconditional Jump	JMP
Jump to Subroutine	JSR

10.1.13 Bit Manipulation Instructions

The CPU can set or clear any writable bit in the first 256 bytes of memor registers, port data direction registers, timer registers, and on-chip RAM loc are in the first 256 bytes of memory. The CPU can also test and branch bas the state of any bit in any of the first 256 memory locations. Bit manip instructions use direct addressing. **Table 10-4** lists these instructions.

Table 10-4. Bit Manipulation Instructions

Instruction	Mnemonic
Clear Bit	BCLR
Branch if Bit Clear	BRCLR
Branch if Bit Set	BRSET
Set Bit	BSET

10.1.14 Control Instructions

These register reference instructions control CPU operation during pr execution. Control instructions, listed in **Table 10-5**, use inherent addressing

Table 10-5. Control Instructions

Instruction	Mnemonic
Clear Carry Bit	CLC
Clear Interrupt Mask	CLI
No Operation	NOP
Reset Stack Pointer	RSP
Return from Interrupt	RTI
Return from Subroutine	RTS
Set Carry Bit	SEC
Set Interrupt Mask	SEI
Stop Oscillator and Enable $\overline{\text{IRQ}}$ Pin	STOP
Software Interrupt	SWI
Transfer Accumulator to Index Register	TAX
Transfer Index Register to Accumulator	TXA
Stop CPU Clock and Enable Interrupts	WAIT

10.1.15 Instruction Set Summary

Table 10-6 is an alphabetical list of all M68HC05 instructions and shows the of each instruction on the condition code register.

Table 10-6. Instruction Set Summary

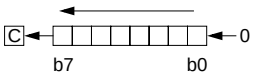
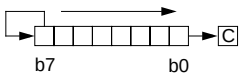
Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand
			H	I	N	Z	C			
ADC #*opr* ADC *opr* ADC *opr* ADC *opr*,X ADC *opr*,X ADC ,X	Add with Carry	A ← (A) + (M) + (C)	↕	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	A9 B9 C9 D9 E9 F9	ii dd hh ee ff
ADD #*opr* ADD *opr* ADD *opr* ADD *opr*,X ADD *opr*,X ADD ,X	Add without Carry	A ← (A) + (M)	↕	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	AB BB CB DB EB FB	ii dd hh ee ff
AND #*opr* AND *opr* AND *opr* AND *opr*,X AND *opr*,X AND ,X	Logical AND	A ← (A) ∧ (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	A4 B4 C4 D4 E4 F4	ii dd hh ee ff
ASL *opr* ASLA ASLX ASL *opr*,X ASL ,X	Arithmetic Shift Left (Same as LSL)		—	—	↕	↕	↕	↕	38 48 58 68 78	dd ff
ASR *opr* ASRA ASRX ASR *opr*,X ASR ,X	Arithmetic Shift Right		—	—	↕	↕	↕	DIR INH INH IX1 IX	37 47 57 67 77	dd ff
BCC *rel*	Branch if Carry Bit Clear	PC ← (PC) + 2 + *rel* ? C = 0	—	—	—	—	—	REL	24	rr
BCLR *n opr*	Clear Bit n	Mn ← 0	—	—	—	—	—	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	11 13 15 17 19 1B 1D 1F	dd dd dd dd dd dd dd dd
BCS *rel*	Branch if Carry Bit Set (Same as BLO)	PC ← (PC) + 2 + *rel* ? C = 1	—	—	—	—	—	REL	25	rr
BEQ *rel*	Branch if Equal	PC ← (PC) + 2 + *rel* ? Z = 1	—	—	—	—	—	REL	27	rr

Table 10-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand
			H	I	N	Z	C			
BHCC *rel*	Branch if Half-Carry Bit Clear	PC ← (PC) + 2 + *rel* ? H = 0	—	—	—	—	—	REL	28	rr
BHCS *rel*	Branch if Half-Carry Bit Set	PC ← (PC) + 2 + *rel* ? H = 1	—	—	—	—	—	REL	29	rr
BHI *rel*	Branch if Higher	PC ← (PC) + 2 + *rel* ? C ∨ Z = 0	—	—	—	—	—	REL	22	rr
BHS *rel*	Branch if Higher or Same	PC ← (PC) + 2 + *rel* ? C = 0	—	—	—	—	—	REL	24	rr
BIH *rel*	Branch if $\overline{IRQ}$ Pin High	PC ← (PC) + 2 + *rel* ? $\overline{IRQ}$ = 1	—	—	—	—	—	REL	2F	rr
BIL *rel*	Branch if $\overline{IRQ}$ Pin Low	PC ← (PC) + 2 + *rel* ? $\overline{IRQ}$ = 0	—	—	—	—	—	REL	2E	rr
BIT #*opr* BIT *opr* BIT *opr* BIT *opr*,X BIT *opr*,X BIT ,X	Bit Test Accumulator with Memory Byte	(A) ∧ (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	A5 B5 C5 D5 E5 F5	ii dd hh ee ff p
BLO *rel*	Branch if Lower (Same as BCS)	PC ← (PC) + 2 + *rel* ? C = 1	—	—	—	—	—	REL	25	rr
BLS *rel*	Branch if Lower or Same	PC ← (PC) + 2 + *rel* ? C ∨ Z = 1	—	—	—	—	—	REL	23	rr
BMC *rel*	Branch if Interrupt Mask Clear	PC ← (PC) + 2 + *rel* ? I = 0	—	—	—	—	—	REL	2C	rr
BMI *rel*	Branch if Minus	PC ← (PC) + 2 + *rel* ? N = 1	—	—	—	—	—	REL	2B	rr
BMS *rel*	Branch if Interrupt Mask Set	PC ← (PC) + 2 + *rel* ? I = 1	—	—	—	—	—	REL	2D	rr
BNE *rel*	Branch if Not Equal	PC ← (PC) + 2 + *rel* ? Z = 0	—	—	—	—	—	REL	26	rr
BPL *rel*	Branch if Plus	PC ← (PC) + 2 + *rel* ? N = 0	—	—	—	—	—	REL	2A	rr
BRA *rel*	Branch Always	PC ← (PC) + 2 + *rel* ? 1 = 1	—	—	—	—	—	REL	20	rr
BRCLR *n opr rel*	Branch if bit n clear	PC ← (PC) + 2 + *rel* ? Mn = 0	—	—	—	—	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 03 05 07 09 0B 0D 0F	dd dd dd dd dd dd dd dd
BRSET *n opr rel*	Branch if Bit n Set	PC ← (PC) + 2 + *rel* ? Mn = 1	—	—	—	—	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 02 04 06 08 0A 0C 0E	dd dd dd dd dd dd dd dd
BRN *rel*	Branch Never	PC ← (PC) + 2 + *rel* ? 1 = 0	—	—	—	—	—	REL	21	rr

Table 10-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand
			H	I	N	Z	C			
BSET *n opr*	Set Bit n	Mn ← 1	—	—	—	—	—	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	10 12 14 16 18 1A 1C 1E	dd dd dd dd dd dd dd dd
BSR *rel*	Branch to Subroutine	PC ← (PC) + 2; push (PCL) SP ← (SP) – 1; push (PCH) SP ← (SP) – 1 PC ← (PC) + *rel*	—	—	—	—	—	REL	AD	rr
CLC	Clear Carry Bit	C ← 0	—	—	—	—	0	INH	98	
CLI	Clear Interrupt Mask	I ← 0	—	0	—	—	—	INH	9A	
CLR *opr* CLRA CLRX CLR *opr*,X CLR ,X	Clear Byte	M ← $00 A ← $00 X ← $00 M ← $00 M ← $00	—	—	0	1	—	DIR INH INH IX1 IX	3F 4F 5F 6F 7F	dd ff
CMP #*opr* CMP *opr* CMP *opr* CMP *opr*,X CMP *opr*,X CMP ,X	Compare Accumulator with Memory Byte	(A) – (M)	—	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	A1 B1 C1 D1 E1 F1	ii dd hh ee ff
COM *opr* COMA COMX COM *opr*,X COM ,X	Complement Byte (One's Complement)	M ← ($\overline{M}$) = $FF – (M) A ← ($\overline{A}$) = $FF – (M) X ← ($\overline{X}$) = $FF – (M) M ← ($\overline{M}$) = $FF – (M) M ← ($\overline{M}$) = $FF – (M)	—	—	↕	↕	1	DIR INH INH IX1 IX	33 43 53 63 73	dd ff
CPX #*opr* CPX *opr* CPX *opr* CPX *opr*,X CPX *opr*,X CPX ,X	Compare Index Register with Memory Byte	(X) – (M)	—	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	A3 B3 C3 D3 E3 F3	ii dd hh ee ff
DEC *opr* DECA DECX DEC *opr*,X DEC ,X	Decrement Byte	M ← (M) – 1 A ← (A) – 1 X ← (X) – 1 M ← (M) – 1 M ← (M) – 1	—	—	↕	↕	—	DIR INH INH IX1 IX	3A 4A 5A 6A 7A	dd ff
EOR #*opr* EOR *opr* EOR *opr* EOR *opr*,X EOR *opr*,X EOR ,X	EXCLUSIVE OR Accumulator with Memory Byte	A ← (A) ⊕ (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	A8 B8 C8 D8 E8 F8	ii dd hh ee ff

Table 10-6. Instruction Set Summary (Continued)

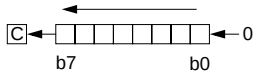
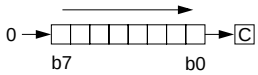
Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand
			H	I	N	Z	C			
INC *opr* INCA INCX INC *opr*,X INC ,X	Increment Byte	M ← (M) + 1 A ← (A) + 1 X ← (X) + 1 M ← (M) + 1 M ← (M) + 1	—	—	↕	↕	—	DIR INH INH IX1 IX	3C 4C 5C 6C 7C	dd ff
JMP *opr* JMP *opr* JMP *opr*,X JMP *opr*,X JMP ,X	Unconditional Jump	PC ← Jump Address	—	—	—	—	—	DIR EXT IX2 IX1 IX	BC CC DC EC FC	dd hh ee ff
JSR *opr* JSR *opr* JSR *opr*,X JSR *opr*,X JSR ,X	Jump to Subroutine	PC ← (PC) + n (n = 1, 2, or 3) Push (PCL); SP ← (SP) – 1 Push (PCH); SP ← (SP) – 1 PC ← Conditional Address	—	—	—	—	—	DIR EXT IX2 IX1 IX	BD CD DD ED FD	dd hh ee ff
LDA #*opr* LDA *opr* LDA *opr* LDA *opr*,X LDA *opr*,X LDA ,X	Load Accumulator with Memory Byte	A ← (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	A6 B6 C6 D6 E6 F6	ii dd hh ee ff
LDX #*opr* LDX *opr* LDX *opr* LDX *opr*,X LDX *opr*,X LDX ,X	Load Index Register with Memory Byte	X ← (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	AE BE CE DE EE FE	ii dd hh ee ff
LSL *opr* LSLA LSLX LSL *opr*,X LSL ,X	Logical Shift Left (Same as ASL)		—	—	↕	↕	↕	DIR INH INH IX1 IX	38 48 58 68 78	dd ff
LSR *opr* LSRA LSRX LSR *opr*,X LSR ,X	Logical Shift Right		—	—	0	↕	↕	DIR INH INH IX1 IX	34 44 54 64 74	dd ff
MUL	Unsigned Multiply	X : A ← (X) × (A)	0	—	—	—	0	INH	42	
NEG *opr* NEGA NEGX NEG *opr*,X NEG ,X	Negate Byte (Two's Complement)	M ← –(M) = $00 – (M) A ← –(A) = $00 – (A) X ← –(X) = $00 – (X) M ← –(M) = $00 – (M) M ← –(M) = $00 – (M)	—	—	↕	↕	↕	DIR INH INH IX1 IX	30 40 50 60 70	ii ff
NOP	No Operation		—	—	—	—	—	INH	9D	

Table 10-6. Instruction Set Summary (Continued)

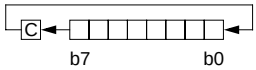
Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand
			H	I	N	Z	C			
ORA #*opr* ORA *opr* ORA *opr* ORA *opr*,X ORA *opr*,X ORA ,X	Logical OR Accumulator with Memory	A ← (A) ∨ (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	AA BA CA DA EA FA	ii dd hh ee ff
ROL *opr* ROLA ROLX ROL *opr*,X ROL ,X	Rotate Byte Left through Carry Bit		—	—	↕	↕	↕	DIR INH INH IX1 IX	39 49 59 69 79	dd ff
ROR *opr* RORA RORX ROR *opr*,X ROR ,X	Rotate Byte Right through Carry Bit		—	—	↕	↕	↕	DIR INH INH IX1 IX	36 46 56 66 76	dd ff
RSP	Reset Stack Pointer	SP ← $00FF	—	—	—	—	—	INH	9C	
RTI	Return from Interrupt	SP ← (SP) + 1; Pull (CCR) SP ← (SP) + 1; Pull (A) SP ← (SP) + 1; Pull (X) SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL)	↕	↕	↕	↕	↕	INH	80	
RTS	Return from Subroutine	SP ← (SP) + 1; Pull (PCH) SP ← (SP) + 1; Pull (PCL)	—	—	—	—	—	INH	81	
SBC #*opr* SBC *opr* SBC *opr* SBC *opr*,X SBC *opr*,X SBC ,X	Subtract Memory Byte and Carry Bit from Accumulator	A ← (A) – (M) – (C)	—	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	A2 B2 C2 D2 E2 F2	ii dd hh ee ff
SEC	Set Carry Bit	C ← 1	—	—	—	—	1	INH	99	
SEI	Set Interrupt Mask	I ← 1	—	1	—	—	—	INH	9B	
STA *opr* STA *opr* STA *opr*,X STA *opr*,X STA ,X	Store Accumulator in Memory	M ← (A)	—	—	↕	↕	—	DIR EXT IX2 IX1 IX	B7 C7 D7 E7 F7	dd hh ee ff
STOP	Stop Oscillator and Enable $\overline{\text{IRQ}}$ Pin		—	0	—	—	—	INH	8E	
STX *opr* STX *opr* STX *opr*,X STX *opr*,X STX ,X	Store Index Register In Memory	M ← (X)	—	—	↕	↕	—	DIR EXT IX2 IX1 IX	BF CF DF EF FF	dd hh ee ff

Table 10-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand
			H	I	N	Z	C			
SUB #*opr* SUB *opr* SUB *opr* SUB *opr*,X SUB *opr*,X SUB ,X	Subtract Memory Byte from Accumulator	A ← (A) – (M)	—	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	A0 B0 C0 D0 E0 F0	ii dd hh ee ff
SWI	Software Interrupt	PC ← (PC) + 1; Push (PCL) SP ← (SP) – 1; Push (PCH) SP ← (SP) – 1; Push (X) SP ← (SP) – 1; Push (A) SP ← (SP) – 1; Push (CCR) SP ← (SP) – 1; I ← 1 PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte	—	1	—	—	—	INH	83	
TAX	Transfer Accumulator to Index Register	X ← (A)	—	—	—	—	—	INH	97	
TST *opr* TSTA TSTX TST *opr*,X TST ,X	Test Memory Byte for Negative or Zero	(M) – $00	—	—	↕	↕	—	DIR INH INH IX1 IX	3D 4D 5D 6D 7D	dd ff
TXA	Transfer Index Register to Accumulator	A ← (X)	—	—	—	—	—	INH	9F	
WAIT	Stop CPU Clock and Enable Interrupts		—	0	—	—	—	INH	8F	

A	Accumulator	*opr*	Operand (one or two bytes)
C	Carry/borrow flag	PC	Program counter
CCR	Condition code register	PCH	Program counter high byte
dd	Direct address of operand	PCL	Program counter low byte
dd rr	Direct address of operand and relative offset of branch instruction	REL	Relative addressing mode
DIR	Direct addressing mode	*rel*	Relative program counter offset byte
ee ff	High and low bytes of offset in indexed, 16-bit offset addressing	rr	Relative program counter offset byte
EXT	Extended addressing mode	SP	Stack pointer
ff	Offset byte in indexed, 8-bit offset addressing	X	Index register
H	Half-carry flag	Z	Zero flag
hh ll	High and low bytes of operand address in extended addressing	#	Immediate value
I	Interrupt mask	∧	Logical AND
ii	Immediate operand byte	∨	Logical OR
IMM	Immediate addressing mode	⊕	Logical EXCLUSIVE OR
INH	Inherent addressing mode	( )	Contents of
IX	Indexed, no offset addressing mode	–( )	Negation (two's complement)
IX1	Indexed, 8-bit offset addressing mode	←	Loaded with
IX2	Indexed, 16-bit offset addressing mode	?	If
M	Memory location	:	Concatenated with
N	Negative flag	↕	Set or cleared
n	Any bit	—	Not affected

Table 10-7. Opcode Map

	Bit Manipulation		Branch	Read-Modify-Write					Control		Register/Mem			
	DIR	DIR	REL	DIR	INH	INH	IX1	IX	INH	INH	IMM	DIR	EXT	IX
MSB / LSB	0	1	2	3	4	5	6	7	8	9	A	B	C	D
0	BRSET0 5 3 DIR	BSET0 5 2 DIR	BRA 3 2 REL	NEG 5 2 DIR	NEGA 3 1 INH	NEGX 3 1 INH	NEG 6 2 IX1	NEG 5 1 IX	RTI 9 1 INH		SUB 2 2 IMM	SUB 3 2 DIR	SUB 4 3 EXT	SU 3
1	BRCLR0 5 3 DIR	BCLR0 5 2 DIR	BRN 3 2 REL						RTS 6 1 INH		CMP 2 2 IMM	CMP 3 2 DIR	CMP 4 3 EXT	CM 3
2	BRSET1 5 3 DIR	BSET1 5 2 DIR	BHI 3 2 REL		MUL 11 1 INH						SBC 2 2 IMM	SBC 3 2 DIR	SBC 4 3 EXT	SB 3
3	BRCLR1 5 3 DIR	BCLR1 5 2 DIR	BLS 3 2 REL	COM 5 2 DIR	COMA 3 1 INH	COMX 3 1 INH	COM 6 2 IX1	COM 5 1 IX	SWI 10 1 INH		CPX 2 2 IMM	CPX 3 2 DIR	CPX 4 3 EXT	CP 3
4	BRSET2 5 3 DIR	BSET2 5 2 DIR	BCC 3 2 REL	LSR 5 2 DIR	LSRA 3 1 INH	LSRX 3 1 INH	LSR 6 2 IX1	LSR 5 1 IX			AND 2 2 IMM	AND 3 2 DIR	AND 4 3 EXT	AN 3
5	BRCLR2 5 3 DIR	BCLR2 5 2 DIR	BCS/BLO 3 2 REL								BIT 2 2 IMM	BIT 3 2 DIR	BIT 4 3 EXT	BI 3
6	BRSET3 5 3 DIR	BSET3 5 2 DIR	BNE 3 2 REL	ROR 5 2 DIR	RORA 3 1 INH	RORX 3 1 INH	ROR 6 2 IX1	ROR 5 1 IX			LDA 2 2 IMM	LDA 3 2 DIR	LDA 4 3 EXT	LD 3
7	BRCLR3 5 3 DIR	BCLR3 5 2 DIR	BEQ 3 2 REL	ASR 5 2 DIR	ASRA 3 1 INH	ASRX 3 1 INH	ASR 6 2 IX1	ASR 5 1 IX		TAX 2 1 INH		STA 4 2 DIR	STA 5 3 EXT	ST 3
8	BRSET4 5 3 DIR	BSET4 5 2 DIR	BHCC 3 2 REL	ASL/LSL 5 2 DIR	ASLA/LSLA 3 1 INH	ASLX/LSLX 3 1 INH	ASL/LSL 6 2 IX1	ASL/LSL 5 1 IX		CLC 2 1 INH	EOR 2 2 IMM	EOR 3 2 DIR	EOR 4 3 EXT	EO 3
9	BRCLR4 5 3 DIR	BCLR4 5 2 DIR	BHCS 3 2 REL	ROL 5 2 DIR	ROLA 3 1 INH	ROLX 3 1 INH	ROL 6 2 IX1	ROL 5 1 IX		SEC 2 1 INH	ADC 2 2 IMM	ADC 3 2 DIR	ADC 4 3 EXT	AD 3
A	BRSET5 5 3 DIR	BSET5 5 2 DIR	BPL 3 2 REL	DEC 5 2 DIR	DECA 3 1 INH	DECX 3 1 INH	DEC 6 2 IX1	DEC 5 1 IX		CLI 2 1 INH	ORA 2 2 IMM	ORA 3 2 DIR	ORA 4 3 EXT	OR 3
B	BRCLR5 5 3 DIR	BCLR5 5 2 DIR	BMI 3 2 REL							SEI 2 1 INH	ADD 2 2 IMM	ADD 3 2 DIR	ADD 4 3 EXT	AD 3
C	BRSET6 5 3 DIR	BSET6 5 2 DIR	BMC 3 2 REL	INC 5 2 DIR	INCA 3 1 INH	INCX 3 1 INH	INC 6 2 IX1	INC 5 1 IX		RSP 2 1 INH		JMP 2 2 DIR	JMP 3 3 EXT	JM 3
D	BRCLR6 5 3 DIR	BCLR6 5 2 DIR	BMS 3 2 REL	TST 4 2 DIR	TSTA 3 1 INH	TSTX 3 1 INH	TST 5 2 IX1	TST 4 1 IX		NOP 2 1 INH	BSR 6 2 REL	JSR 5 2 DIR	JSR 6 3 EXT	JS 3
E	BRSET7 5 3 DIR	BSET7 5 2 DIR	BIL 3 2 REL						STOP 2 1 INH		LDX 2 2 IMM	LDX 3 2 DIR	LDX 4 3 EXT	LD 3
F	BRCLR7 5 3 DIR	BCLR7 5 2 DIR	BIH 3 2 REL	CLR 5 2 DIR	CLRA 3 1 INH	CLRX 3 1 INH	CLR 6 2 IX1	CLR 5 1 IX	WAIT 2 1 INH	TXA 2 1 INH		STX 4 2 DIR	STX 5 3 EXT	ST 3

INH = Inherent
IMM = Immediate
DIR = Direct
EXT = Extended
REL = Relative
IX = Indexed, No Offset
IX1 = Indexed, 8-Bit Offset
IX2 = Indexed, 16-Bit Offset

LSB of Opcode in Hexadecimal

MSB / LSB	0
0	BRSET0 5 3 DIR

MSB of Opcode i
Number of Cycles
Opcode Mnemon
Number of Bytes/Ad

SECTION 11
ELECTRICAL SPECIFICATIONS

This section provides the electrical and timing specifications fo MC68HC05J5A.

11.1 MAXIMUM RATINGS

(Voltages referenced to V_{SS})

Rating	Symbol	Value	U
Supply Voltage	V_{DD}	–0.3 to +7.0	
Test Mode ($\overline{IRQ}$ Pin Only)	V_{IN}	V_{SS} – 0.3 to $2V_{DD}$ + 0.3	
Current Drain Per Pin Excluding PB1, PB2, V_{DD} and V_{SS}	I	25	
Operating Junction Temperature	T_J	+150	
Storage Temperature Range	T_{stg}	–65 to +150	

NOTE

Maximum ratings are the extreme limits the device can be exposed to v causing permanent damage to the chip. The device is **not** intended to ope these conditions.

The MCU contains circuitry that protect the inputs against damage fror static voltages; however, do not apply voltages higher than those shown table below. Keep V_{IN} and V_{OUT} within the range from $V_{SS} \le (V_{IN}$ or $V_{OUT})$ Connect unused inputs to the appropriate voltage level, either V_{SS} or V_{DD}.

11.2 THERMAL CHARACTERISTICS

Characteristic	Symbol	Value
Thermal Resistance PDIP SOIC	 θ_{JA} θ_{JA}	 60 60

11.3 FUNCTIONAL OPERATING RANGE

Characteristic	Symbol	Value
Operating Temperature Range	T_A	0 to +70
Operating Voltage Range	V_{DD}	5.0 ±10% 2.2 ±10%

11.4 DC ELECTRICAL CHARACTERISTICS

Table 11-1. DC Electrical Characteristics, V_{DD}=5 V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Output Voltage I_{Load} = 10.0 µA	V_{OL} V_{OH}	— V_{DD} – 0.1	— —	0.1 —
Output High Voltage (I_{Load} =–0.8 mA) PA0-5, PB0, PB3-5	V_{OH}	V_{DD} – 0.8	—	—
Output Low Voltage (I_{Load} = 1.6mA) PA0-3, PB0, PB3-5 (I_{Load} = 8mA) PA4-7 (I_{Load} = 25mA) PB1, PB2 (see note 8)	V_{OL}	— — —	— — —	0.4 0.4 0.5
Input High Voltage PA0-5, PB0-5, $\overline{IRQ}$, $\overline{RESET}$, OSC1	V_{IH}	0.7×V_{DD}	—	V_{DD}
Input Low Voltage PA0-5, PB0-5, $\overline{IRQ}$, $\overline{RESET}$, OSC1	V_{IL}	V_{SS}	—	0.2×V_{DD}
Positive-Going Input Threshold Voltage PA6, PA7	V_{T+}	—	1.7	—
Negative-Going Input Threshold Voltage PA6, PA7	$V_{T–}$	—	1.15	—
Supply Current RUN[3] WAIT[4] STOP[5] LVR on LVR off	I_{DD}	 — — — —	 6 2 40 20	 8 4 80 40
I/O Ports Hi-Z Leakage Current PA0-7, PB0-5 (without individual pull-down/up activated)	I_Z	—	—	±10
Input Pull-down Current PA0-5, PB0, PB3-5 (with individual pull-down activated)	I_{IL}	50	100	200
Input Pull-up Current $\overline{RESET}$	—	–140	–180	–240
Input Current $\overline{IRQ}$, OSC1	I_{in}	—	—	±1
Capacitance Ports (as Input or Output) $\overline{RESET}$, $\overline{IRQ}$, OSC1, OSC2/R	C_{out} C_{in}	— —	— —	12 8
Crystal/Ceramic Resonator Oscillator Mode Internal Resistor OSC1 to OSC2/R	R_{OSC}	—	3	—

Table 11-1. DC Electrical Characteristics, V_{DD}=5 V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Pull-up Resistor PA6, PA7[6] PB1, PB2	R_{PULLUP}	 2 15	 5 30	 10 60
LVR Trigger Voltage	V_{LVRI}	2.52	2.8	—
TCAP Input Threshold Voltage	V_{TCAP}	—	$V_{DD}/2$	—

1. V_{DD} = 5.0 Vdc ±10%, V_{SS} = 0 Vdc, T_A = 0°C to +70°C, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25°C only.
3. Run (Operating) I_{DD}, Wait I_{DD}: Measured using external square wave clock source to OSC1 (f_{OSC} = 2.0 M inputs 0.2 Vdc from rail; no DC loads, less than 50pF on all outputs, C_L = 20 pF on OSC2/R.
4. Wait I_{DD}: Only MFT and Timer1 active.
   Wait I_{DD} is affected linearly by the OSC2/R capacitance.
5. Stop I_{DD} measured with OSC1 = V_{SS}.
6. Input voltage level on PA6 or PA7 higher than 2.4V is guaranteed to be recognized as logical one and a zero if lower than 0.8V. PA6 and PA7 pull-up resistor values are specified under the condition that pin ranges from 0V to 2.4V.

Table 11-2. DC Electrical Characteristics, V_{DD}=2.2 V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Output Voltage I_{Load} = 10.0 µA	V_{OL} V_{OH}	— V_{DD} – 0.1	— —	0.1 —
Output High Voltage (I_{Load} = –0.4 mA) PA0-5, PB0, PB3-5	V_{OH}	V_{DD} – 0.3	—	—
Output Low Voltage (I_{Load} = 0.8 mA) PA0-3, PB0, PB3-5 (I_{Load} = 2 mA) PA4-7 (I_{Load} = 8 mA) PB1, PB2 (see note 8)	V_{OL}	 — — —	 — — —	 0.3 0.3 0.4
Input High Voltage PA0-5, PB0-5, $\overline{IRQ}$, $\overline{RESET}$, OSC1	V_{IH}	0.7×V_{DD}	—	V_{DD}
Input Low Voltage PA0-5, PB0-5, $\overline{IRQ}$, $\overline{RESET}$, OSC1	V_{IL}	V_{SS}	—	0.2×V_{DD}
Positive-Going Input Threshold Voltage PA6, PA7	V_{T+}	—	0.7	—
Negative-Going Input Threshold Voltage PA6, PA7	V_{T-}	—	0.5	—
Supply Current RUN[3] WAIT[4] STOP[5] (LVR off)	I_{DD}	 — — —	 1 0.2 6	 2 0.4 15

Table 11-2. DC Electrical Characteristics, V_{DD}=2.2V

Characteristic[1]	Symbol	Min	Typ[2]	Max
I/O Ports Hi-Z Leakage Current PA0-7, PB0-5 (without individual pull-down/up activated)	I_Z	—	—	±10
Input Pull-down Current PA0-5, PB0, PB3-5 (with individual pull-down activated)	I_{IL}	50	100	200
Input Pull-up Current $\overline{RESET}$	—	–10	–20	–45
Input Current $\overline{IRQ}$, OSC1	I_{in}	—	—	±1
Capacitance Ports (as Input or Output) $\overline{RESET}$, $\overline{IRQ}$, OSC1, OSC2/R	C_{out} C_{in}	— —	— —	12 8
Crystal/Ceramic Resonator Oscillator Mode Internal Resistor OSC1 to OSC2/R	R_{OSC}	—	3	—
Pull-up Resistor PA6, PA7[6] PB1, PB2	R_{PULLUP}	2 15	5 30	10 60
LVR Trigger Voltage	LVR must be disabled (mask option) for V_{DD}=			
TCAP Input Threshold Voltage	V_{TCAP}	—	$V_{DD}/2$	—

1. V_{DD} = 2.2Vdc ±10%, V_{SS} = 0 Vdc, T_A = 0°C to +70°C, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25°C only.
3. Run (Operating) I_{DD}, Wait I_{DD}: Measured using external square wave clock source to OSC1 (f_{OSC} = 2.0 M inputs 0.2 Vdc from rail; no DC loads, less than 50pF on all outputs, C_L = 20 pF on OSC2/R.
4. Wait I_{DD}: Only MFT and Timer1 active.
   Wait I_{DD} is affected linearly by the OSC2/R capacitance.
5. Stop I_{DD} measured with OSC1 = V_{SS}.
6. Input voltage level on PA6 or PA7 higher than 2.4V is guaranteed to be recognized as logical one and a zero if lower than 0.8V. PA6 and PA7 pull-up resistor values are specified under the condition that pin ranges from 0V to 2.4V.

11.5 CONTROL TIMING

Table 11-3. Control Timing, V_{DD}=5V

Characteristic[1]	Symbol	Min	Max	U
Frequency of Operation Crystal Oscillator Option External Clock Source	 f_{OSC} f_{OSC}	 — DC	 4.2 4.2	 M M
Internal Operating Frequency Crystal Oscillator ($f_{OSC} \div 2$) External Clock ($f_{OSC} \div 2$)	 f_{OP} f_{OP}	 — DC	 2.1 2.1	 M M
Cycle Time ($1/f_{OP}$)	t_{CYC}	415	—	
$\overline{\text{RESET}}$ Pulse Width Low	t_{RL}	1.5	—	t
$\overline{\text{IRQ}}$ Interrupt Pulse Width Low (Edge-Triggered)	t_{ILIH}	0.5	—	t
$\overline{\text{IRQ}}$ Interrupt Pulse Period	t_{ILIL}	see note[2]	—	t
PA0 to PA3 Interrupt Pulse Width High (Edge-Triggered)	t_{IHIL}	0.5	—	t
PA0 to PA3 Interrupt Pulse Period	t_{IHIH}	see note 3	—	t
PA7 Interrupt Pulse Width Low	t_{ILIH}	0.5	—	t
OSC1 Pulse Width	t_{OH}, t_{OL}	200	—	
Output High to Low Transition Period on PA6, PA7, PB1[3]	t_{SLOW}	0.5 (typical)		t

1. V_{DD} = 5.0Vdc ±10%, V_{SS} = 0 Vdc, T_A = 0°C to +70°C, unless otherwise noted.
2. The minimum period t_{ILIL} or t_{IHIH} should not be less than the number of cycles it takes to execute the in service routine plus 19 t_{CYC}.
3. t_{slow} is a parameter dependent on f_{OSC} and loading.

Table 11-4. Control Timing, V_{DD}=2.2V

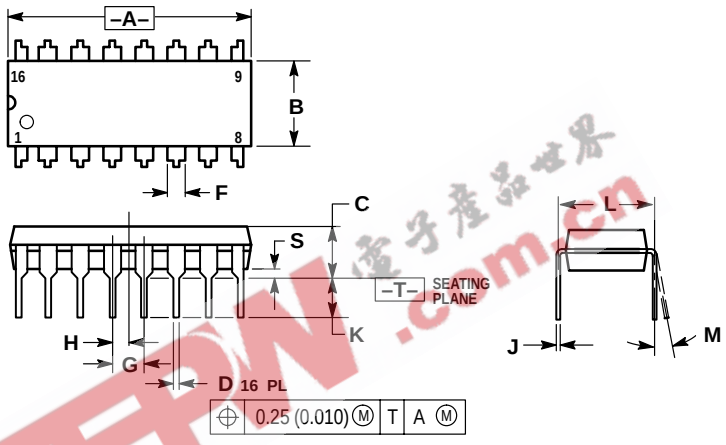
Characteristic[1]	Symbol	Min	Max	U
Frequency of Operation Crystal Oscillator Option External Clock Source	 f_{OSC} f_{OSC}	 — DC	 2.1 2.1	 M M

1. V_{DD} = 2.2Vdc ±10%, V_{SS} = 0 Vdc, T_A = 0°C to +70°C, unless otherwise noted.

SECTION 12
MECHANICAL SPECIFICATIONS

This section provides the mechanical dimensions for the four available pac
for MC68HC05J5A.

12.1 16-PIN PDIP (CASE #648)

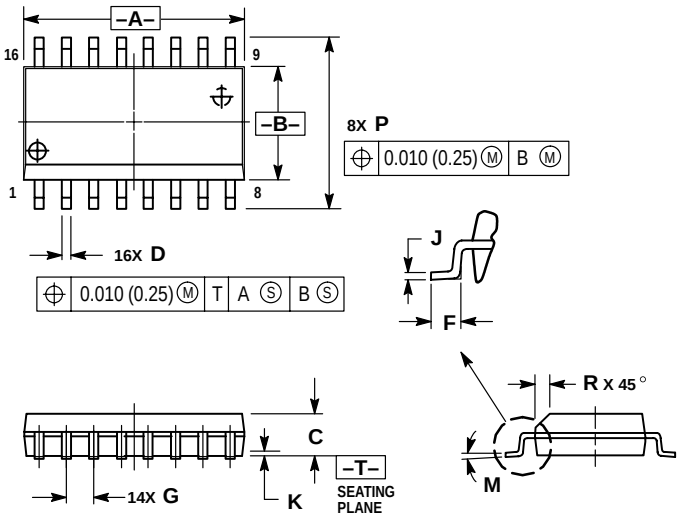


NOTES:
1. DIMENSIONING AND TOLERANCING PER
Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHI
FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

Figure 12-1. 16-Pin PDIP Mechanical Dimensions

12.2 16-PIN SOIC (CASE #751G)

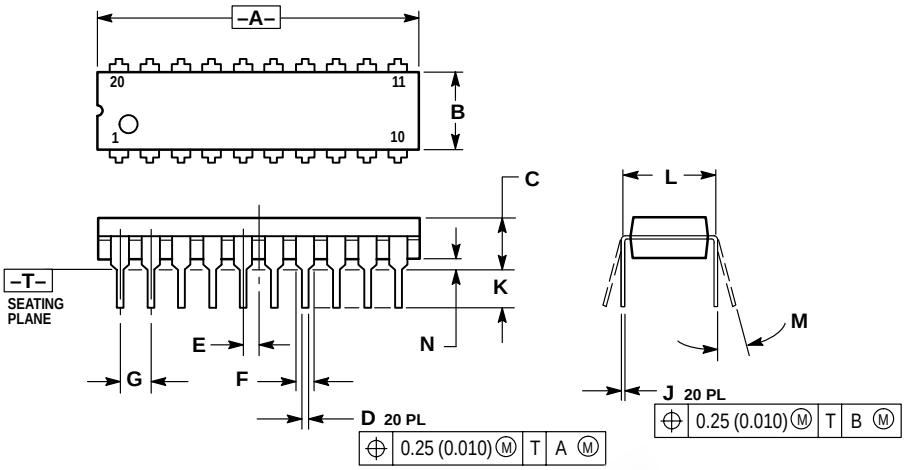


NOTES:
1. DIMENSIONING AND TOLERANCING PER AN
Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MO
PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR
PROTRUSION. ALLOWABLE DAMBAR
PROTRUSION SHALL BE 0.13 (0.005) TOTAL
EXCESS OF D DIMENSION AT MAXIMUM
MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

Figure 12-2. 16-Pin SOIC Mechanical Dimensions

12.3 20-PIN PDIP (CASE #738)

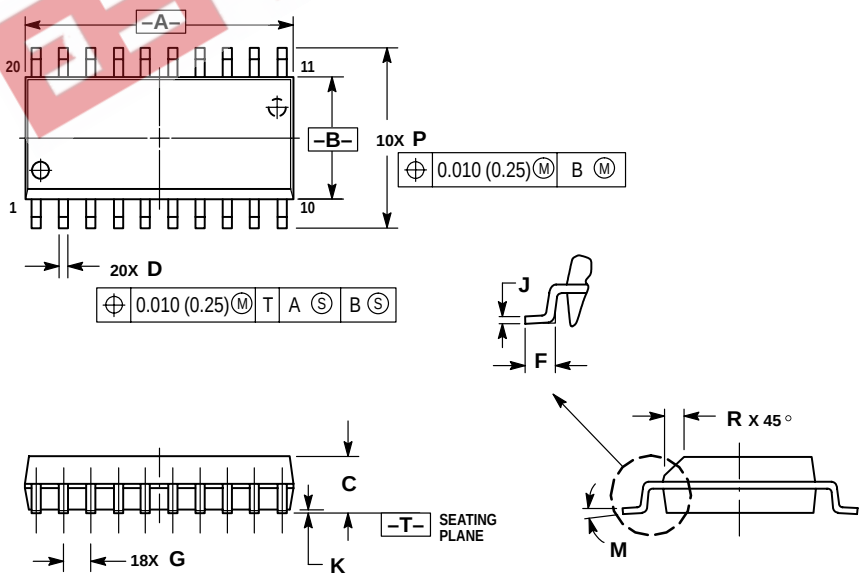


NOTES:
1. DIMENSIONING AND TOLERANCIN Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. DIMENSION L TO CENTER OF LEA FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUD FLASH.

	INCHES		MILLIME
DIM	MIN	MAX	MIN
A	1.010	1.070	25.66
B	0.240	0.260	6.10
C	0.150	0.180	3.81
D	0.015	0.022	0.39
E	0.050 BSC		1.27 B
F	0.050	0.070	1.27
G	0.100 BSC		2.54 B
J	0.008	0.015	0.21
K	0.110	0.140	2.80
L	0.300 BSC		7.62 B
M	0 °	15 °	0 °
N	0.020	0.040	0.51

Figure 12-3. 20-Pin PDIP Mechanical Dimensions

12.4 20-PIN SOIC (CASE #751D)



NOTES:
1. DIMENSIONING AND TOLERANCIN ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLI
3. DIMENSIONS A AND B DO NOT INC MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.1 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWAB DAMBAR PROTRUSION SHALL BE (0.005) TOTAL IN EXCESS OF D DI AT MAXIMUM MATERIAL CONDITIO

	MILLIMETERS		INCH
DIM	MIN	MAX	MIN
A	12.65	12.95	0.499
B	7.40	7.60	0.292
C	2.35	2.65	0.093
D	0.35	0.49	0.014
F	0.50	0.90	0.020
G	1.27 BSC		0.050
J	0.25	0.32	0.010
K	0.10	0.25	0.004
M	0 °	7 °	0 °
P	10.05	10.55	0.395
R	0.25	0.75	0.010

Figure 12-4. 20-Pin SOIC Mechanical Dimensions

APPENDIX A
MC68HRC05J5A

This appendix describes the MC68HRC05J5A, a resistor-capacitor (RC) os mask option version of the MC68HC05J5A. The entire MC68HC05J5A data applies to the MC68HRC05J5A, with exceptions outlined in this appendix.

A.1 INTRODUCTION

The MC68HRC05J5A is a resistor-capacitor (RC) oscillator mask option v of the MC68HC05J5A. The MC68HRC05J5A is functionally identical MC68HC05J5A with the exception that the MC68HRC05J5A supports t oscillator only, as outlined in **Appendix A.2**.

A.2 RC OSCILLATOR CONNECTIONS

This is the only oscillator option supported by the MC68HRC05J5A device.

On the MC68HRC05J5A device, an external resistor is connected be OSC2/R pin and the V_{SS} pin as shown in **Figure A-1**. The typical operati quency f_{OSC} is set at 4MHz with the external R tied to V_{SS}. Use the gr **Figure A-2** to select the value of R for the required oscillator frequency.

The tolerance of this RC oscillator is guaranteed to be no greater than ±1 the specified conditions of 0°C to 40°C and 5V ±10% V_{DD} providing that the ance of the external resistor R is at most ±1% and the center frequency ra from 3.8MHz to 4.2MHz. The center frequency is the nominal operating freq of the RC oscillator and can be adjusted by adjusting the external R va change the internal VCO charging current.

In order to obtain an oscillator clock with the best possible tolerance, the ex resistor connected to the OSC2/R pin should be grounded as close to the V as possible and the other terminal of this external resistor should be connec close to the OSC2/R pin as possible.

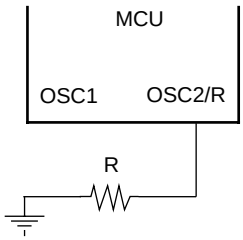


Figure A-1. RC Oscillator Connections

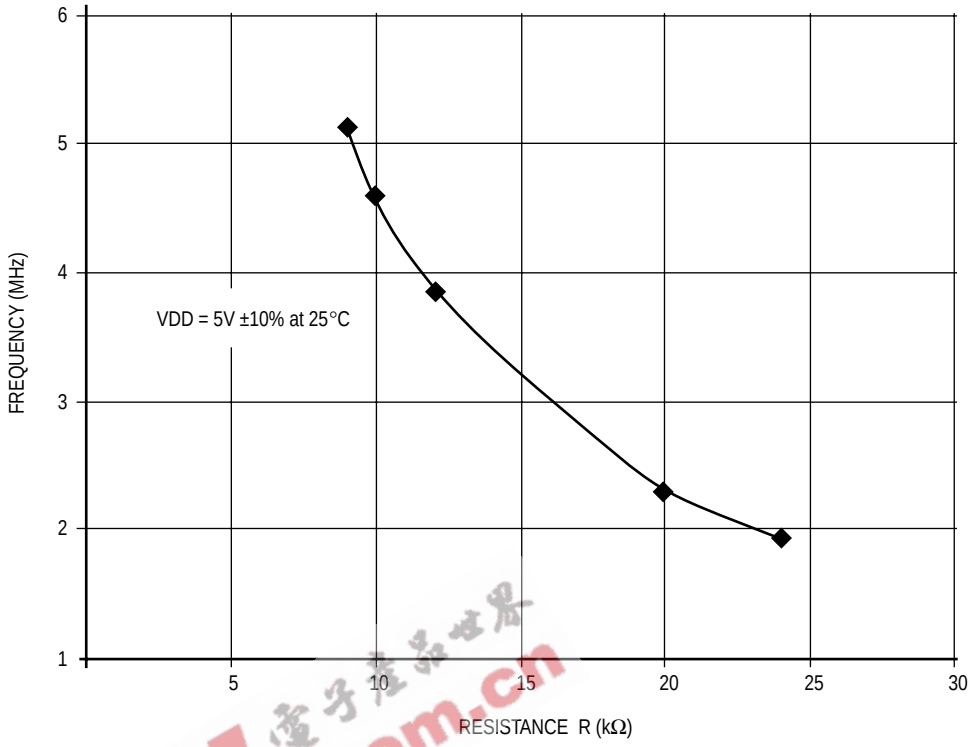


Figure A-2. Typical Internal Operating Frequency for RC Oscillator Connections

A.3 ELECTRICAL CHARACTERISTICS

Table A-1. Functional Operating Range

Characteristic	Symbol	Value
Operating Temperature Range	T_A	0 to +70
Operating Voltage Range	V_{DD}	5.0 ±10%

Table A-2. DC Electrical Characteristics, V_{DD}=5V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Supply Current				
RUN[3]	I_{DD}	—	6	8
WAIT[4]		—	2	4
STOP				
LVR on		—	40	80
LVR off		—	20	40

1. V_{DD} = 5.0 Vdc ±10%, V_{SS} = 0 Vdc, T_A = 0°C to +70°C, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25°C only.
3. Run (Operating) I_{DD}, Wait I_{DD}: Measured using external square wave clock source to OSC1 (f_{OSC} = 2.0 M inputs 0.2 Vdc from rail; no DC loads, less than 50pF on all outputs, C_L = 20 pF on OSC2/R.
4. Wait I_{DD}: Only MFT and Timer1 active.
   Wait I_{DD} is affected linearly by the OSC2/R capacitance.

APPENDIX B
MC68HC705J5A

This appendix describes the MC68HC705J5A, the emulation pa
MC68HC05J5A. The entire MC68HC05J5A data sheet applies t
MC68HC705J5A, with exceptions outlined in this appendix.

B.1 INTRODUCTION

The MC68HC705J5A is an EPROM version of the MC68HC05J5A, and is
able for user system evaluation and debugging. The MC68HC705J5A is fu
ally identical to the MC68HC05J5A with the exception of the 2560 byte
ROM is replaced by 2560 bytes user EPROM. Also, the mask options availa
the MC68HC05J5A are implemented using the Mask Option Register (M
the MC68HC705J5A.

The MC68HC705J5A is not available in the 16-pin SOIC package.

B.2 MEMORY

The MC68HC705J5A memory map is shown in **Figure B-1**.

B.3 MASK OPTION REGISTERS (MOR)

The Mask Option Register (MOR) consists of two bytes of EPROM used to
the features controlled by mask options on the MC68HC05J5A. In order
gram this register the MORON bit in PCR need to be set to “1” before doi
EPROM programming process.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	
MOR1	R			STOPMD	IRQTRIG	PULLREN	PAINTEN	OSCDLY	L
$0200	W								
erased:		X	X	1	1	1	1	1	
reset:		Unaffected by reset							

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	
MOR2	R								C
$0201	W								
erased:		0	0	0	0	0	0	0	
reset:		Unaffected by reset							

STOPMD — STOP Mode Option

1 = STOP mode is selected.
0 = STOP mode is converted to HALT mode.

IRQTRIG — IRQ, PA0-PA3 Interrupt Option

1 = Edge-triggered only.
0 = Edge-and-level-triggered.

PULLREN — Port A and B Pull-up/down Option

1 = Connected.
0 = Disconnected

PAINTEN — PA0-PA3 External Interrupt Option

1 = External interrupt capability on PA0-PA3 disabled.
0 = External interrupt capability on PA0-PA3 enabled.

OSCDLY — Oscillator Delay Option

1 = 224 internal clock cycles.
0 = 4064 internal clock cycles.

LVREN — LVR Option

1 = Low Voltage Reset circuit enabled.
0 = Low Voltage Reset circuit disabled.

COP_EN — COP Watchdog Timer Option

1 = Disabled.
0 = Enabled.

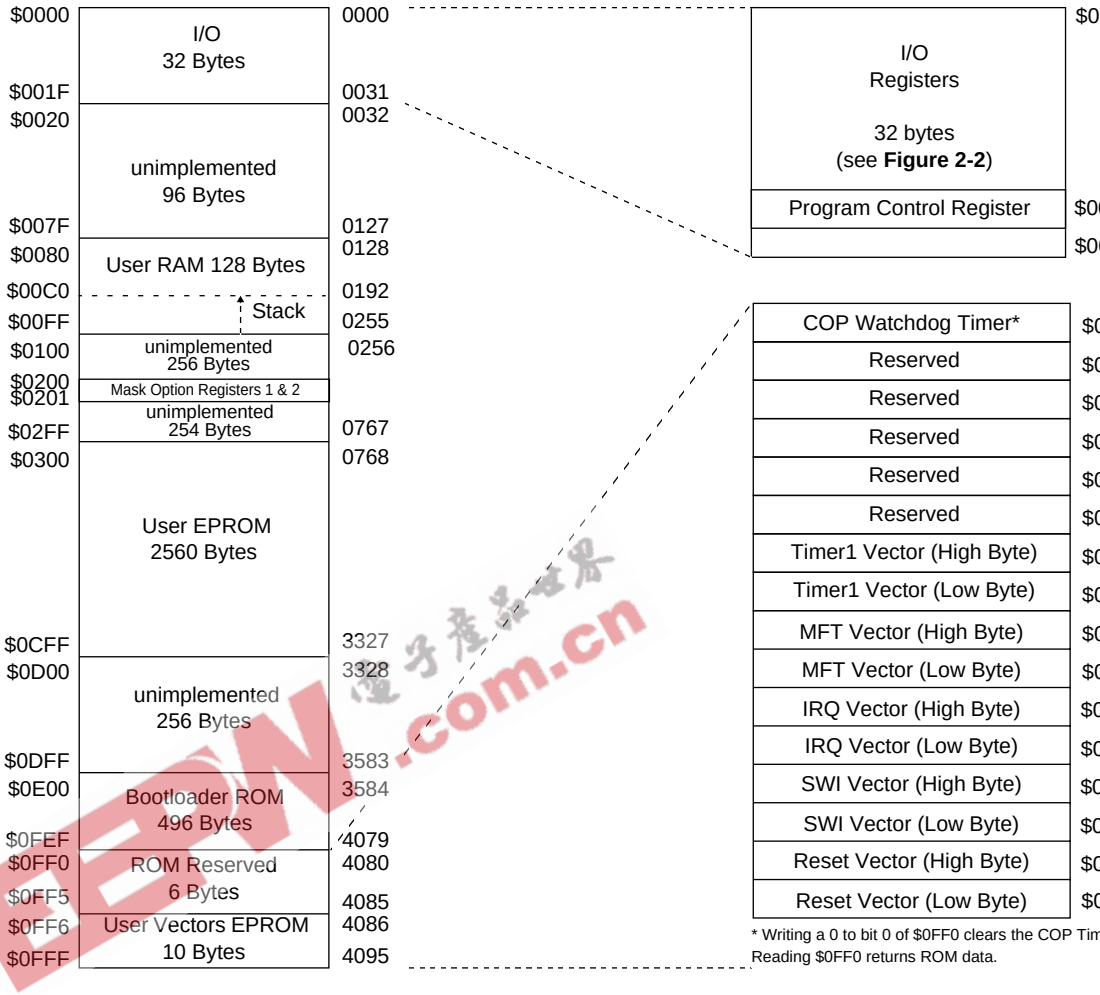


Figure B-1. MC68HC705J5A Memory Map

B.4 BOOTSTRAP MODE

Bootloader mode is entered upon the rising edge of $\overline{\text{RESET}}$ if the $\overline{\text{IRQ}}/V_{PP}$ at V_{TST} and the PB0 pin is at logic zero. The Bootloader program is masked ROM area from $0E00 to $0FEF. This program handles copying of user cod an external EPROM into the on-chip EPROM. The bootload function has done from an external EPROM. The bootloader performs one programmin at 1ms per byte then does a verify pass.

The user code must be a one-to-one correspondence with the internal E addresses.

B.5 EPROM PROGRAMMING

Programming the on-chip EPROM is achieved by using the Program Contro ister located at address $3E.

Please contact Motorola for programming board availability.

B.5.1 EPROM Program Control Register (PCR)

This register is provided for programming the on-chip EPROM i MC68HC705J5A.

		BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1
PCR	R	0	0	0	0	0	MORON	ELAT
$001E	W	R	R	R	R	R		
reset:		0	0	0	0	0	0	0

R = Reserved

MORON – Mask Option Register ON

0 = Disable programming to Mask Option Register ($0200 & $0201)
1 = Enable programming to Mask Option Register ($0200 & $0201)

ELAT – EPROM LATch control

0 = EPROM address and data bus configured for normal reads
1 = EPROM address and data bus configured for programming (wr to EPROM cause address and data to be latched). EPROM i programming mode and cannot be read if ELAT is 1. This bit sho not be set when no programming voltage is applied to the V_{pp} pi

PGM – EPROM ProGraM command

0 = Programming power is switched OFF from EPROM array.
1 = Programming power is switched ON to EPROM array. If ELAT = then PGM = 0.

Bits [7:3] – Reserved

These are reserved bits and should remain zero.

B.5.2 Programming Sequence

The EPROM programming sequence is:

1. Set the ELAT bit
2. Write the data to the address to be programmed
3. Set the PGM bit
4. Delay for a time t_{PGMR}
5. Clear the PGM bit
6. Clear the ELAT bit

The last two steps must be performed with separate CPU writes.

CAUTION

It is important to remember that an external programming voltage must be a to the V_{PP} pin while programming, but it should be equal to V_{DD} during r operations.

Figure B-2 shows the flow required to successfully program the EPROM.

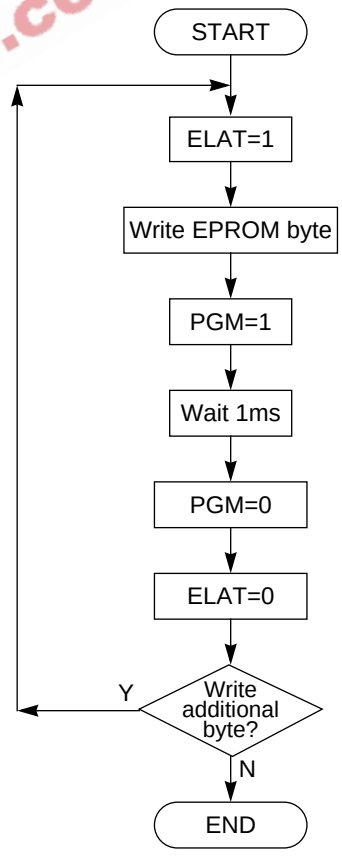


Figure B-2. EPROM Programming Sequence

B.6 ELECTRICAL CHARACTERISTICS

Table B-1. Functional Operating Range

Characteristic	Symbol	Value
Operating Temperature Range	T_A	–40 to +85
Operating Voltage Range	V_{DD}	5.0 ±10%

Table B-2. EPROM Programming Electrical Characteristics

Characteristic	Symbol	Min	Typ	Max
Programming Voltage $\overline{IRQ}/V_{PP}$	V_{PP}	10	12	15
Programming Current $\overline{IRQ}/V_{PP}$	I_{PP}	—	3	—
Programming Time per byte	t_{EPGM}	1	4	—

Table B-3. DC Electrical Characteristics, V_{DD}=5 V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Output Voltage I_{Load} = 10.0 µA	V_{OL} V_{OH}	— V_{DD} – 0.1	— —	0.1 —
Output High Voltage (I_{Load} = –0.8 mA) PA0-5, PB0, PB3-5	V_{OH}	V_{DD} – 0.8	—	—
Output Low Voltage (I_{Load} = 1.6 mA) PA0-3, PB0, PB3-5 (I_{Load} = 8 mA) PA4, PA5 (I_{Load} = 6 mA) PA6, PA7 (I_{Load} = 25 mA) PB1, PB2 (see note 8)	V_{OL}	— — — —	— — — —	0.4 0.4 0.4 0.5
Input High Voltage PA0-5, PB0-5, $\overline{IRQ}$, $\overline{RESET}$, OSC1	V_{IH}	0.7×V_{DD}	—	V_{DD}
Input Low Voltage PA0-5, PB0-5, $\overline{IRQ}$, $\overline{RESET}$, OSC1	V_{IL}	V_{SS}	—	0.2×V_{DD}
Positive-Going Input Threshold Voltage PA6, PA7	V_{T+}	—	1.7	—
Negative-Going Input Threshold Voltage PA6, PA7	$V_{T–}$	—	1.15	—

Table B-3. DC Electrical Characteristics, V_{DD}=5 V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Supply Current				
RUN[3]	I_{DD}	—	6	10
WAIT[4]		—	2	4
STOP[5]				
LVR on		—	40	80
LVR off		—	10	30
I/O Ports Hi-Z Leakage Current PA0-7, PB0-5 (without individual pull-down/up activated)	I_Z	—	—	±10
Input Pull-down Current PA0-5, PB0, PB3-5 (with individual pull-down activated)	I_{IL}	50	100	200
Input Pull-up Current $\overline{RESET}$	—	–50	–100	–200
Input Current $\overline{IRQ}$, OSC1	I_{in}	—	—	±1
Capacitance				
Ports (as Input or Output)	C_{out}	—	—	12
$\overline{RESET}$, $\overline{IRQ}$, OSC1, OSC2/R	C_{in}	—	—	8
Crystal/Ceramic Resonator Oscillator Mode Internal Resistor OSC1 to OSC2/R	R_{OSC}	—	2	—
Pull-up Resistor				
PA6, PA7[6]	R_{PULLUP}	2	5	10
PB1, PB2		10	30	60
LVR Trigger Voltage	V_{LVRI}	2.7	3.0	—
TCAP Input Threshold Voltage	V_{TCAP}	—	$V_{DD}/2$	—

1. V_{DD} = 5.0 Vdc ±10%, V_{SS} = 0 Vdc, T_A = –40°C to +85°C, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25°C only.
3. Run (Operating) I_{DD}, Wait I_{DD}: Measured using external square wave clock source to OSC1 (f_{OSC} = 2.0 M inputs 0.2 Vdc from rail; no DC loads, less than 50pF on all outputs, C_L = 20 pF on OSC2/R.
4. Wait I_{DD}: Only MFT and Timer1 active.
   Wait I_{DD} is affected linearly by the OSC2/R capacitance.
5. Stop I_{DD} measured with OSC1 = V_{SS}.
6. Input voltage level on PA6 or PA7 higher than 2.4V is guaranteed to be recognized as logical one and a zero if lower than 0.8V. PA6 and PA7 pull-up resistor values are specified under the condition that pin ranges from 0V to 2.4V.

APPENDIX C
MC68HRC705J5A

This appendix describes the MC68HRC705J5A, the emulation pa MC68HRC05J5A, and a resistor-capacitor (RC) oscillator mask option vers the MC68HC705J5A. The entire MC68HC05J5A data sheet and appe applies to the MC68HRC705J5A, with exceptions outlined in this appendix.

C.1 INTRODUCTION

The MC68HRC705J5A is a resistor-capacitor (RC) oscillator mask option v of the MC68HC705J5A (see **Appendix B**). The MC68HRC705J5A is funct identical to the MC68HC705J5A with the exception that the MC68HRC7 supports the RC oscillator only, as outlined in **Appendix C.2**.

The MC68HRC705J5A is not available in the 16-pin SOIC package.

C.2 RC OSCILLATOR CONNECTIONS

This is the only oscillator option supported by the MC68HRC705J5A device

On the MC68HRC705J5A device, an external resistor is connected be OSC2/R pin and the V_{SS} pin as shown in **Figure C-1**. The typical operati quency f_{OSC} is set at 4MHz with the external R tied to V_{SS}. Use the gr **Figure C-2** to select the value of R for the required oscillator frequency.

The tolerance of this RC oscillator is guaranteed to be no greater than ±1 the specified conditions of 0°C to 40°C and 5V ±10% V_{DD} providing that the ance of the external resistor R is at most ±1% and the center frequency ra from 3.8MHz to 4.2MHz. The center frequency is the nominal operating freq of the RC oscillator and can be adjusted by adjusting the external R va change the internal VCO charging current.

In order to obtain an oscillator clock with the best possible tolerance, the ex resistor connected to the OSC2/R pin should be grounded as close to the V as possible and the other terminal of this external resistor should be connec close to the OSC2/R pin as possible.

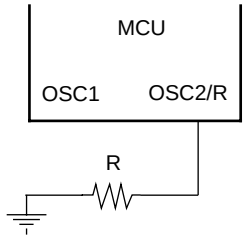


Figure C-1. RC Oscillator Connections

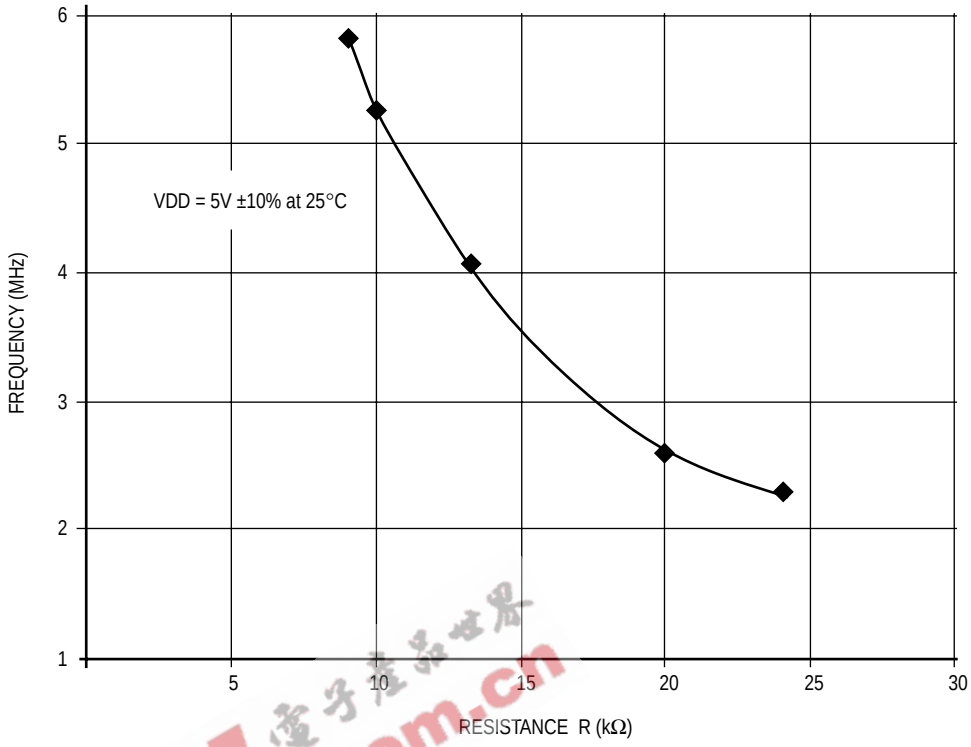


Figure C-2. Typical Internal Operating Frequency for RC Oscillator Connect

C.3 ELECTRICAL CHARACTERISTICS

Table C-1. Functional Operating Range

Characteristic	Symbol	Value
Operating Temperature Range	T_A	–40 to +85
Operating Voltage Range	V_{DD}	5.0 ±10%

Table C-2. DC Electrical Characteristics, V_{DD}=5 V

Characteristic[1]	Symbol	Min	Typ[2]	Max
Supply Current				
RUN[3]	I_{DD}	—	6	10
WAIT[4]		—	2	4
STOP[5]				
LVR on		—	40	80
LVR off		—	10	30

1. V_{DD} = 5.0Vdc ±10%, V_{SS} = 0 Vdc, T_A = –40°C to +85°C, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25°C only.
3. Run (Operating) I_{DD}, Wait I_{DD}: Measured using external square wave clock source to OSC1 (f_{OSC} = 2.0 M inputs 0.2 Vdc from rail; no DC loads, less than 50pF on all outputs, C_L = 20 pF on OSC2/R.
4. Wait I_{DD}: Only MFT and Timer1 active.
   Wait I_{DD} is affected linearly by the OSC2/R capacitance.
5. Stop I_{DD} measured with OSC1 = V_{SS}.

APPENDIX D
ORDERING INFORMATION

This section contains ordering numbers for the MC68HC0 MC68HRC05J5A, MC68HC705J5A, and MC68HRC705J5A.

D.1 MC ORDER NUMBERS

Table D-1. MC Order Numbers

MC Order Number	Pin Count	Package Type	Operating Temperature	Device Type
MC68HC05J5AJP	16	PDIP	0 °C to +70 °C	2560 bytes ROM, crystal/resonator or exte oscillator option
MC68HC05J5AJDW	16	SOIC		
MC68HC05J5AP	20	PDIP		
MC68HC05J5ADW	20	SOIC		
MC68HRC05J5AJP	16	PDIP	0 °C to +70 °C	2560 bytes ROM, RC oscillator option
MC68HRC05J5AJDW	16	SOIC		
MC68HRC05J5AP	20	PDIP		
MC68HRC05J5ADW	20	SOIC		
MC68HC705J5ACJP	16	PDIP	–40 °C to +85 °C	2560 bytes OTPROM, crystal/resonator or exte oscillator option
MC68HC705J5ACP	20	PDIP		
MC68HC705J5ACDW	20	SOIC		
MC68HRC705J5ACJP	16	PDIP	–40 °C to +85 °C	2560 bytes OTPROM, RC oscillator option
MC68HRC705J5ACP	20	PDIP		
MC68HRC705J5ACDW	20	SOIC		

NOTES:
C = extended temperature
P = plastic dual-in-line package (PDIP)
DW = small outline integrated circuit (SOIC)